

FIG. 1

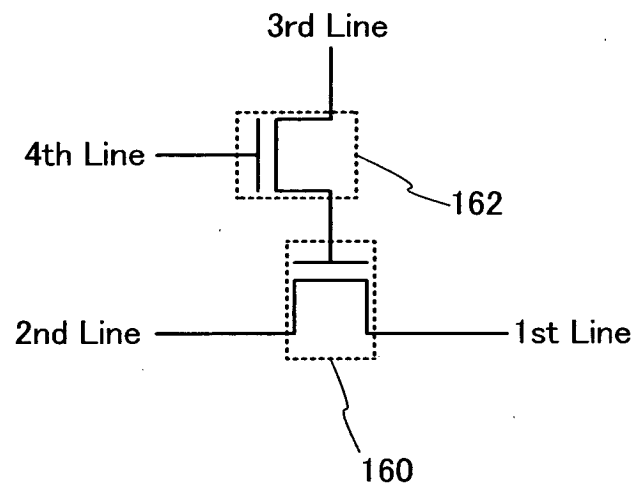


FIG. 2A

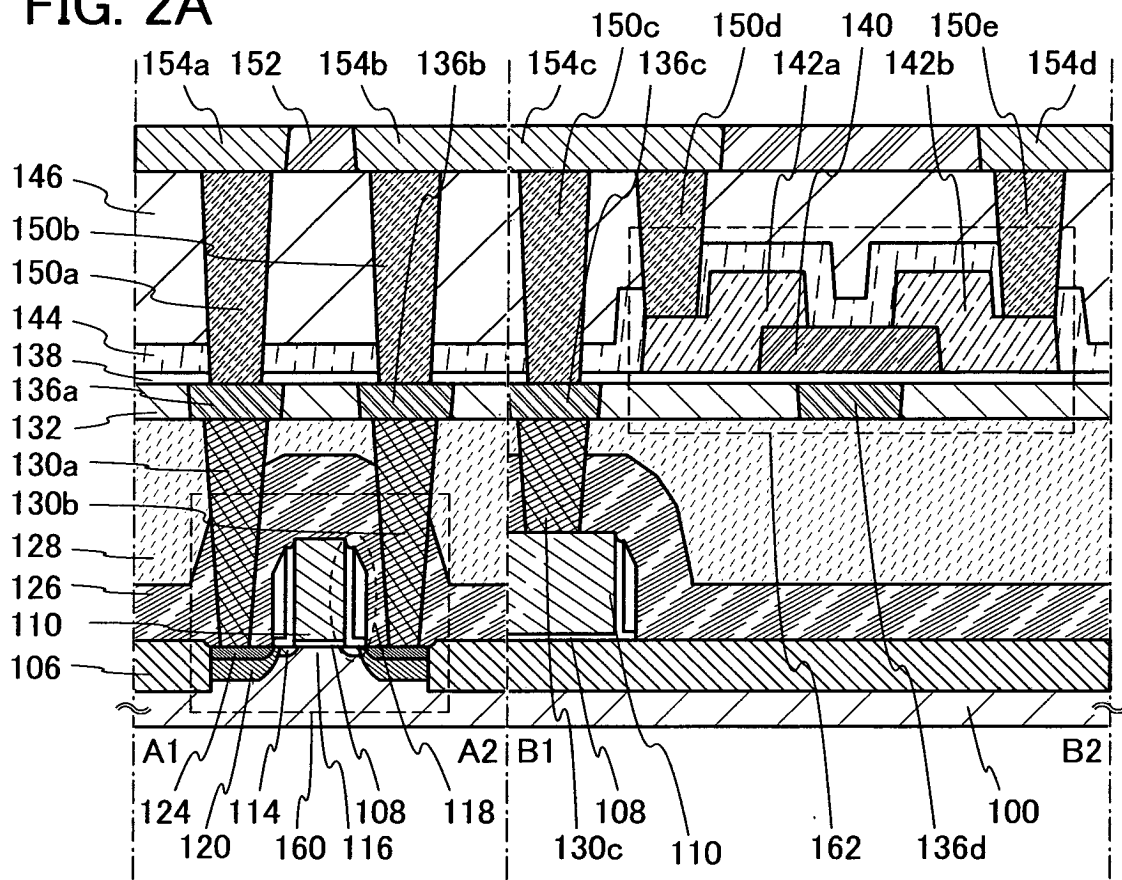


FIG. 2B

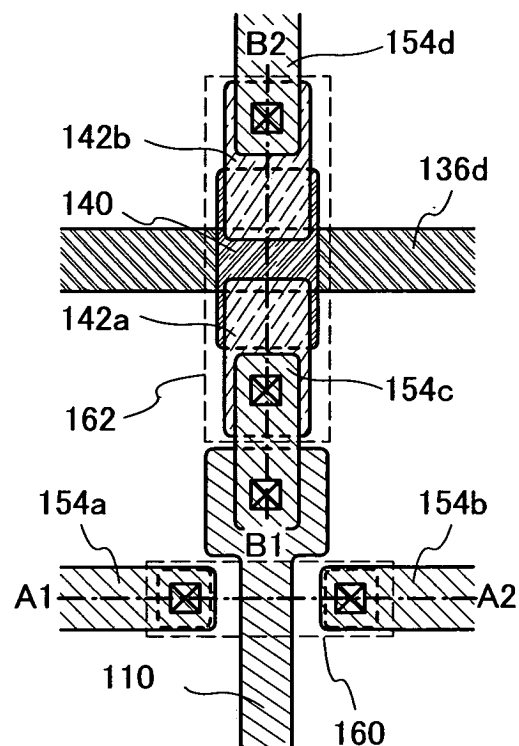


FIG. 3A

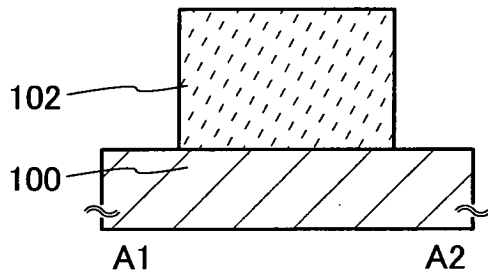


FIG. 3E

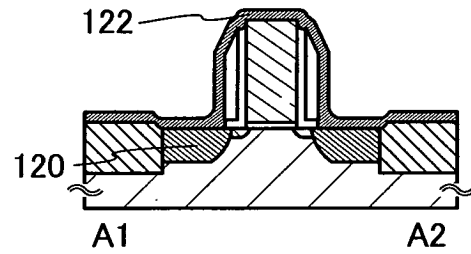


FIG. 3B

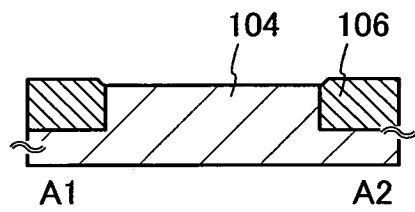


FIG. 3F

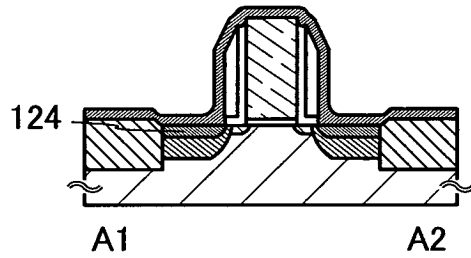


FIG. 3C

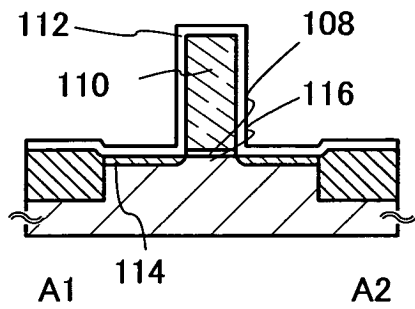


FIG. 3G

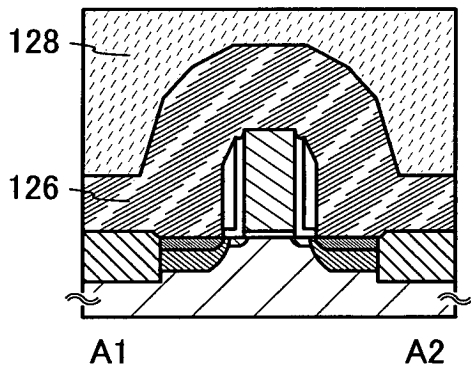


FIG. 3D

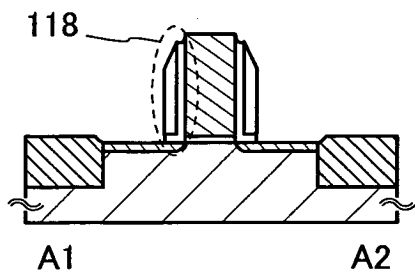


FIG. 3H

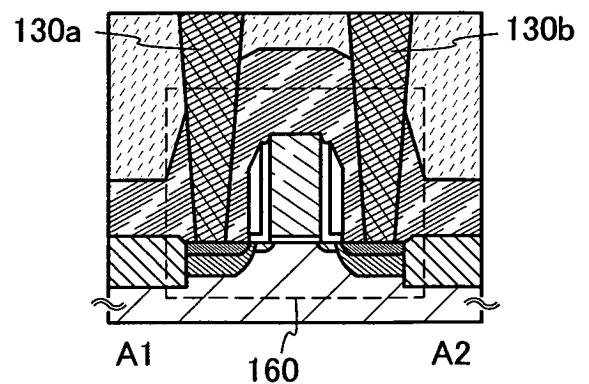


FIG. 4A

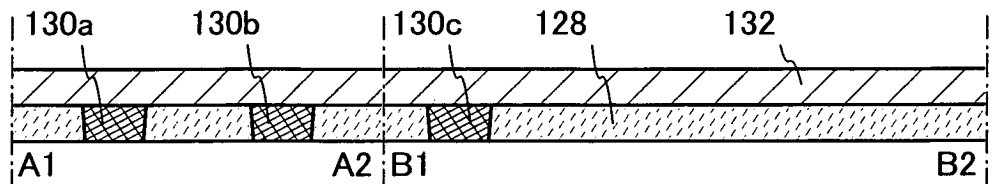


FIG. 4B

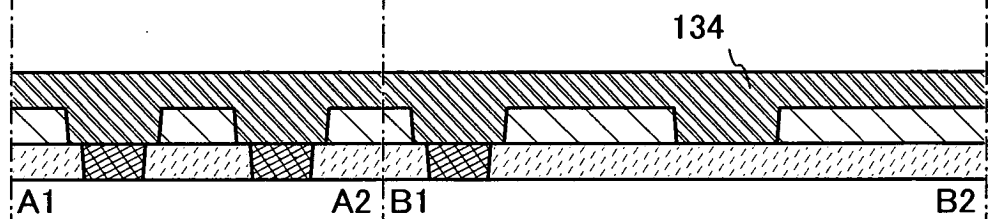


FIG. 4C

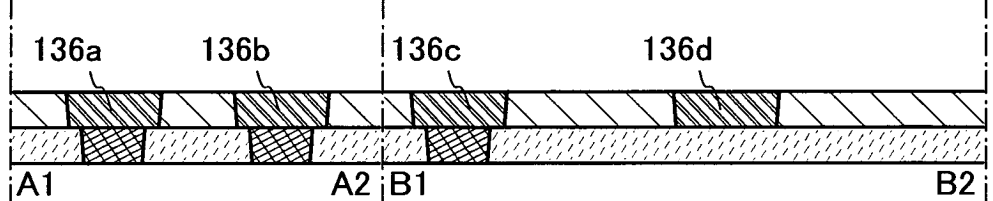


FIG. 4D

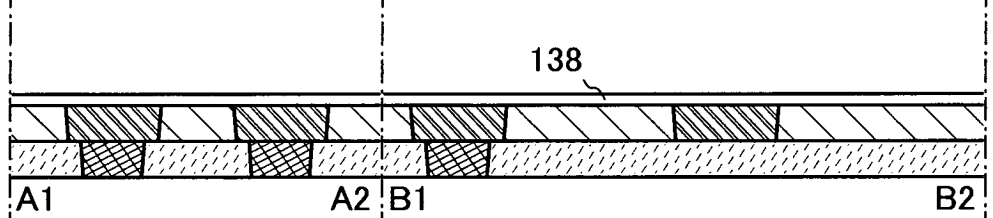


FIG. 4E

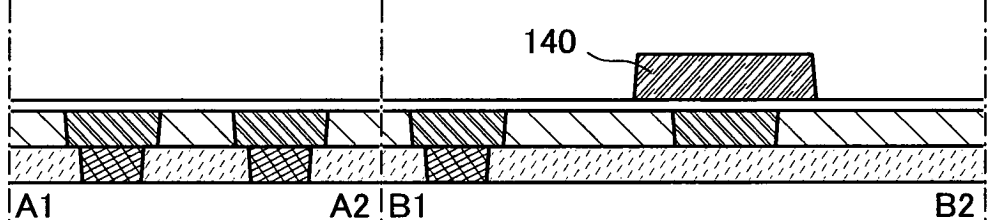


FIG. 4F

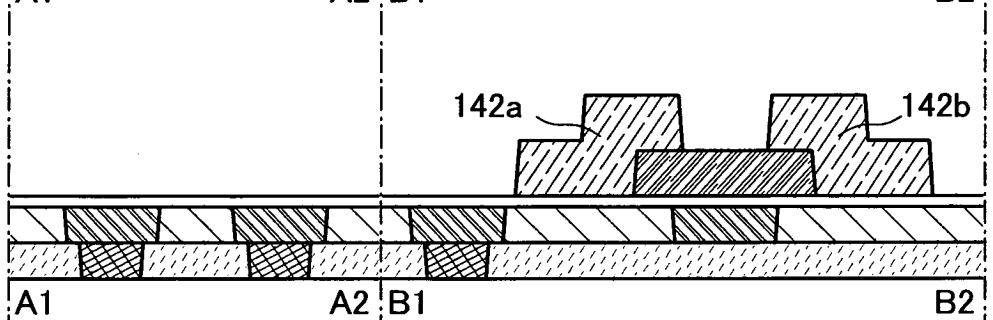


FIG. 4G

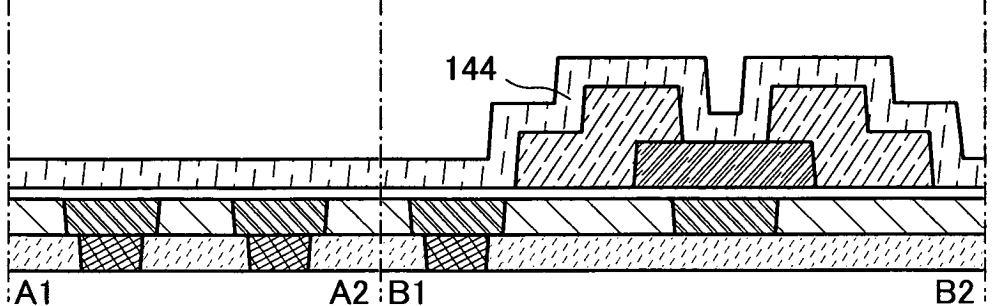


FIG. 5A

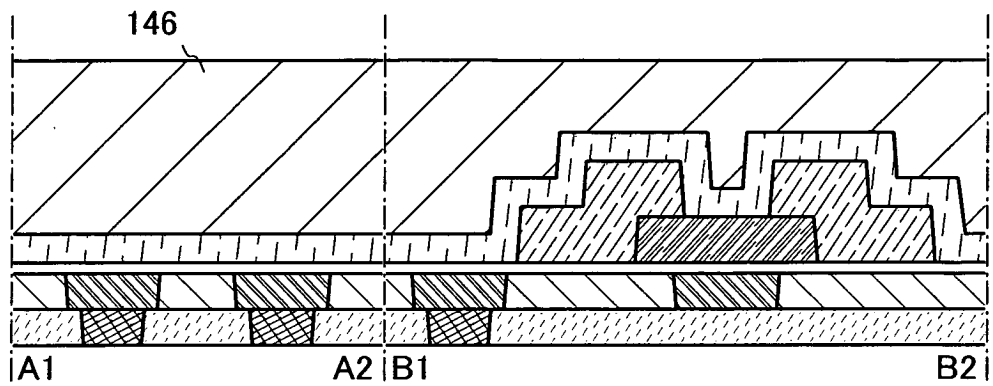


FIG. 5B

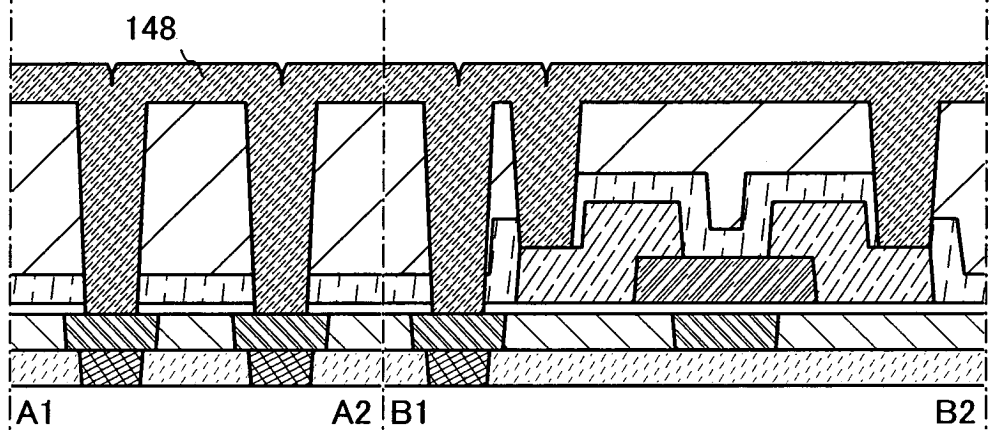


FIG. 5C

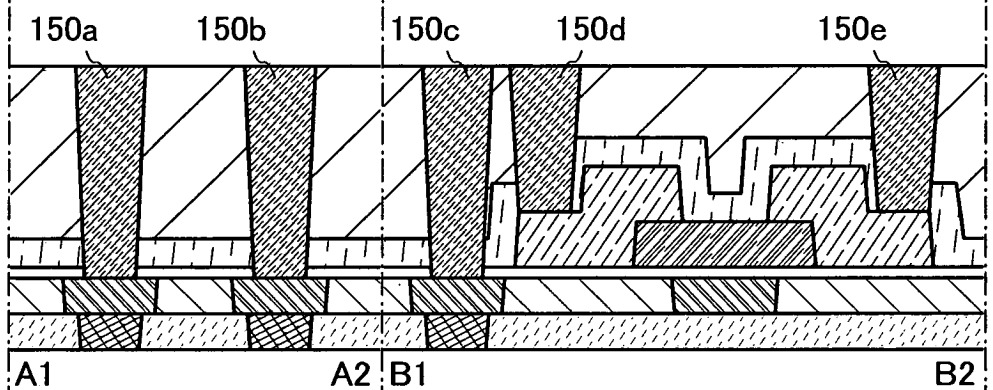


FIG. 5D

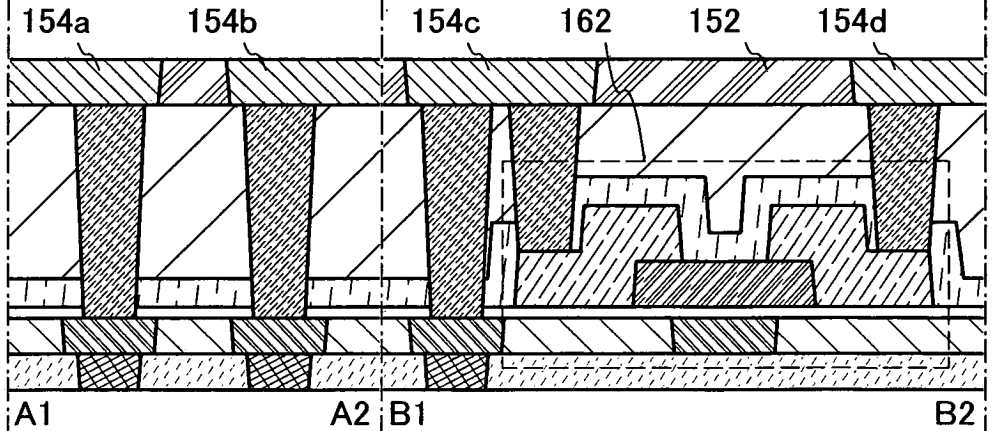


FIG. 6

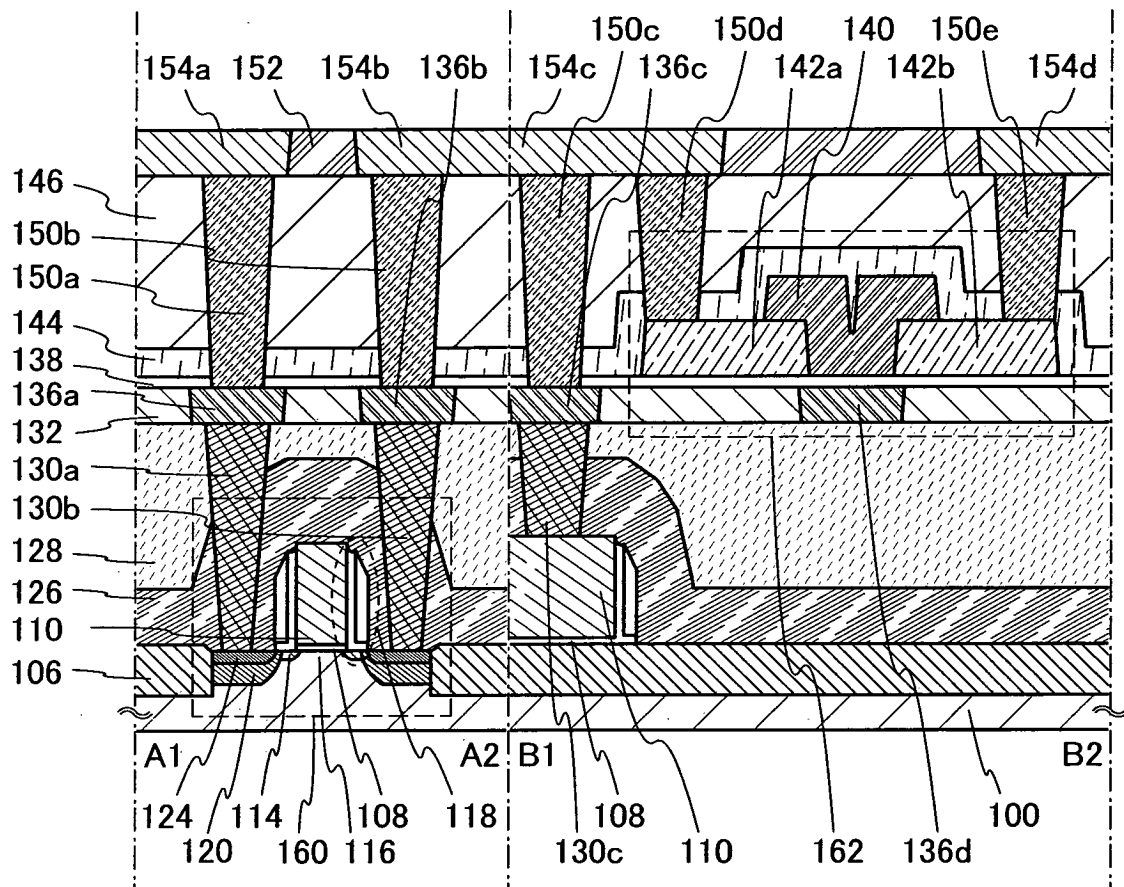


FIG. 7A

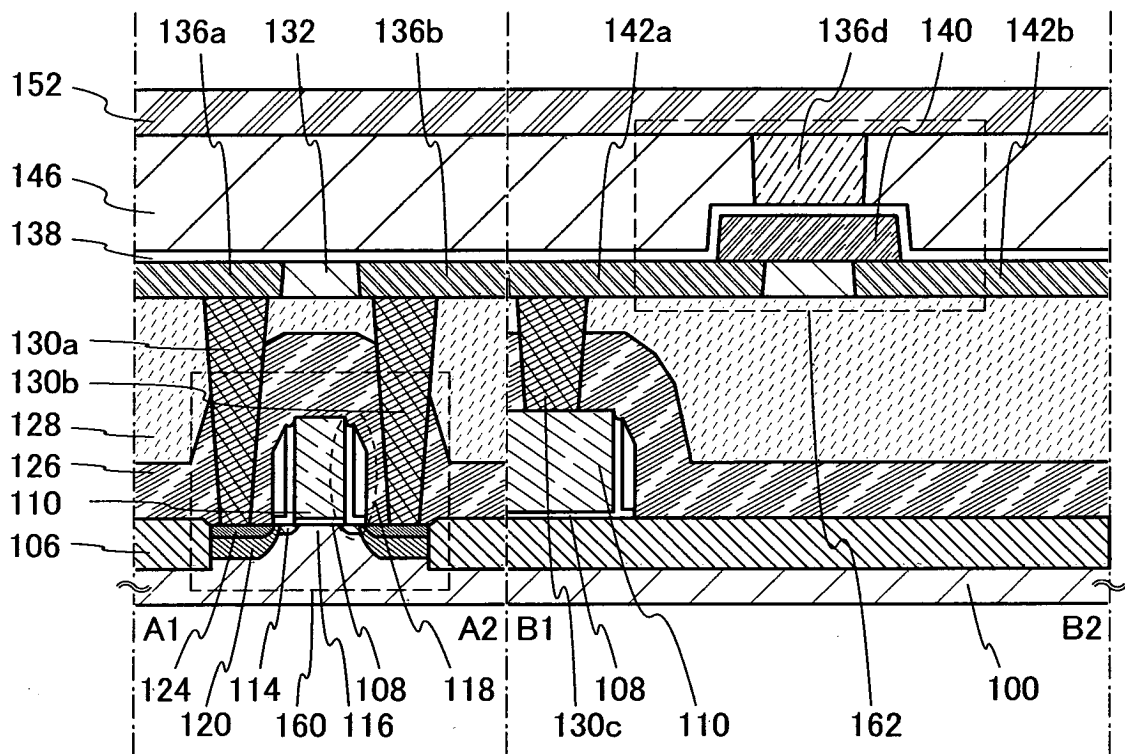


FIG. 7B

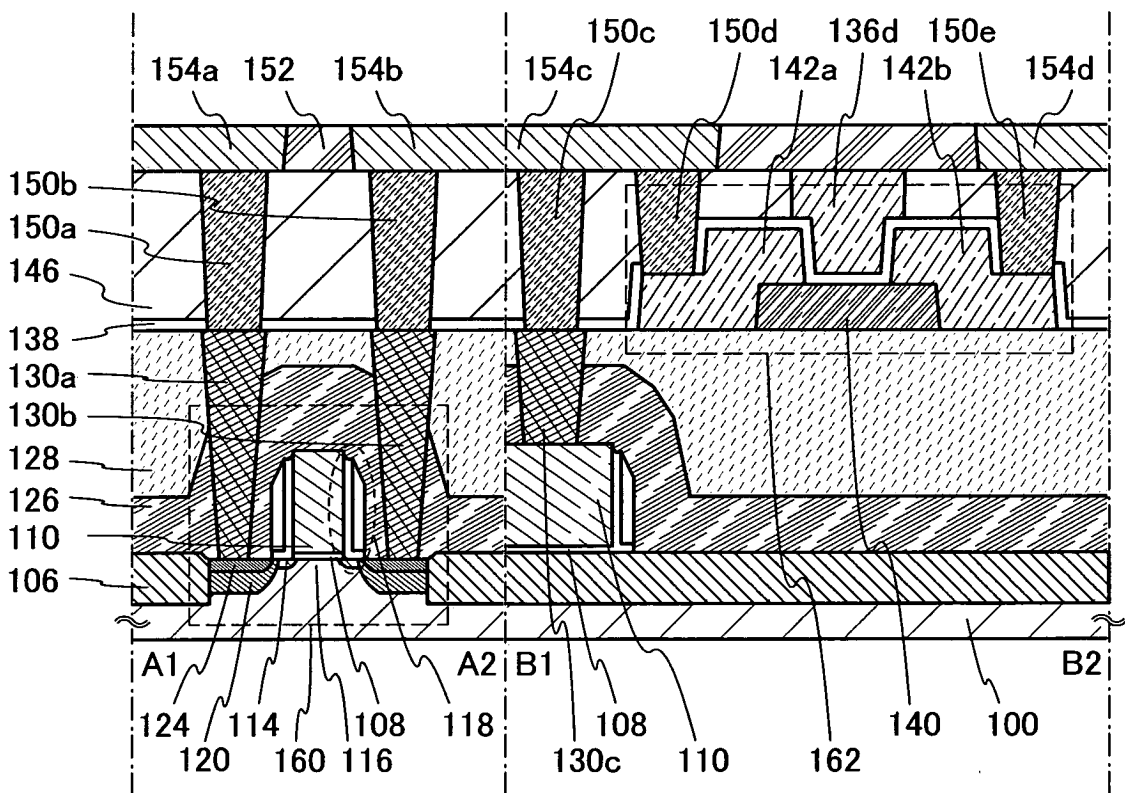


FIG. 8A

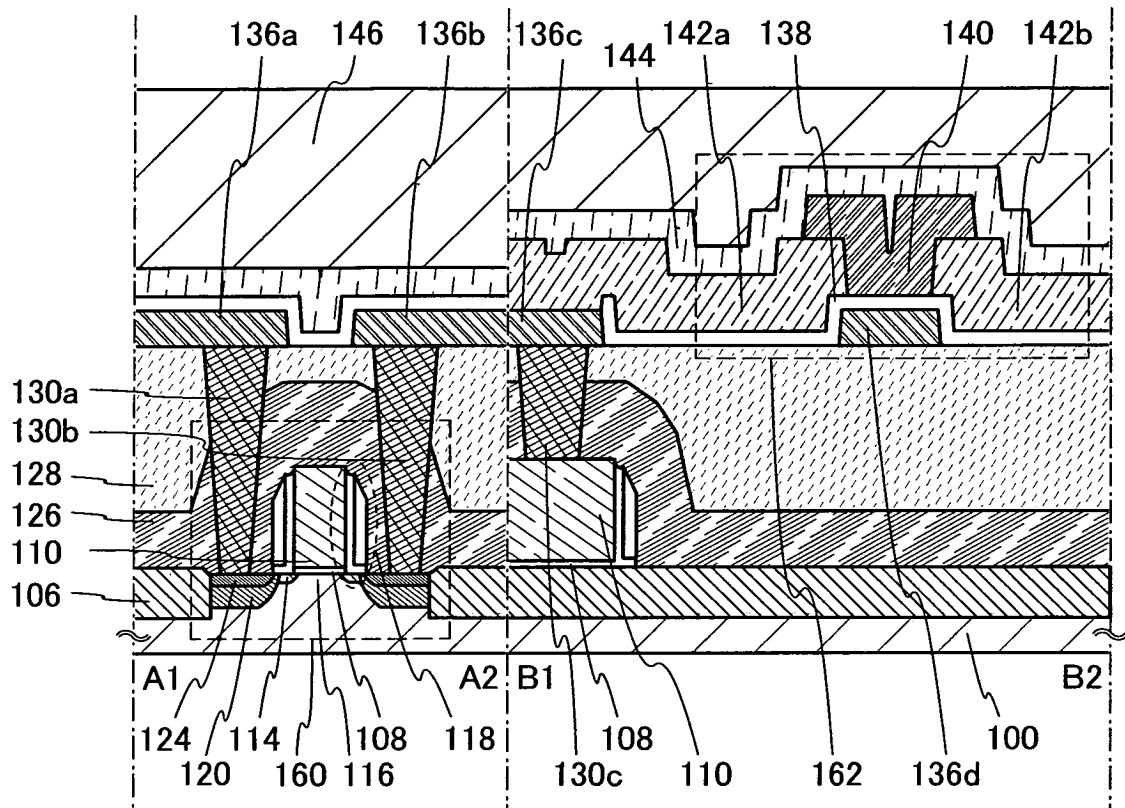


FIG. 8B

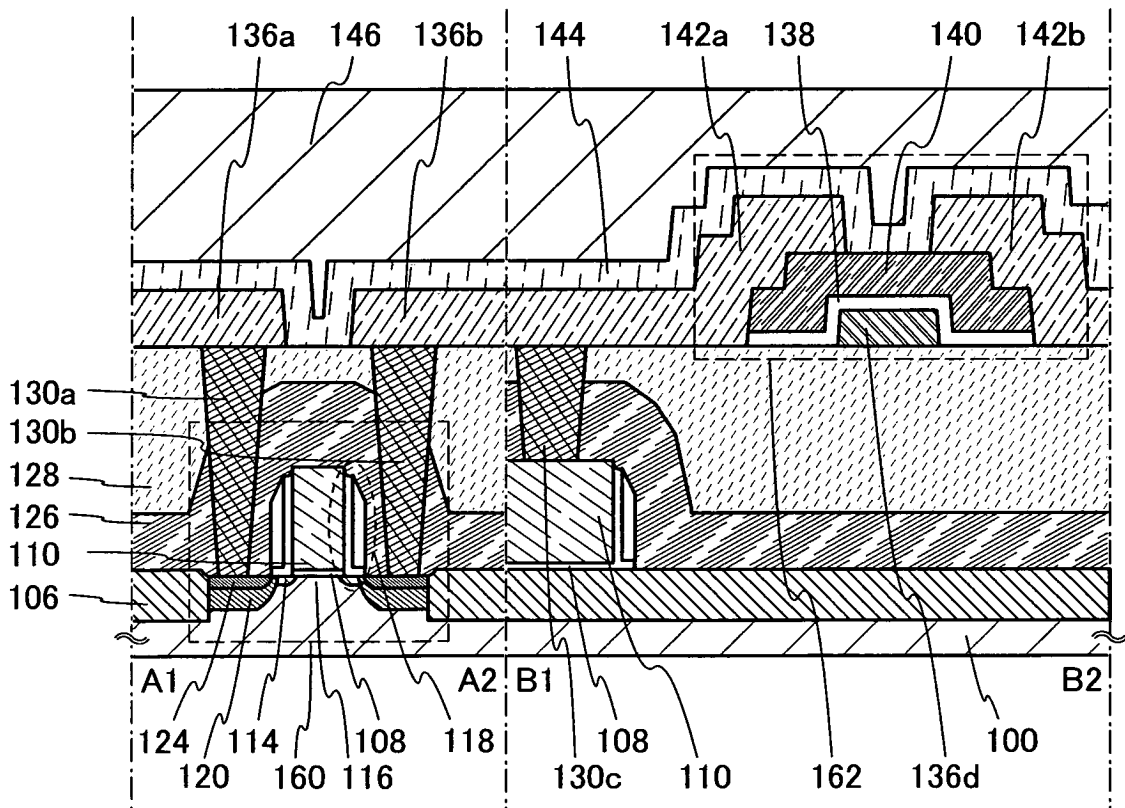


FIG. 9A

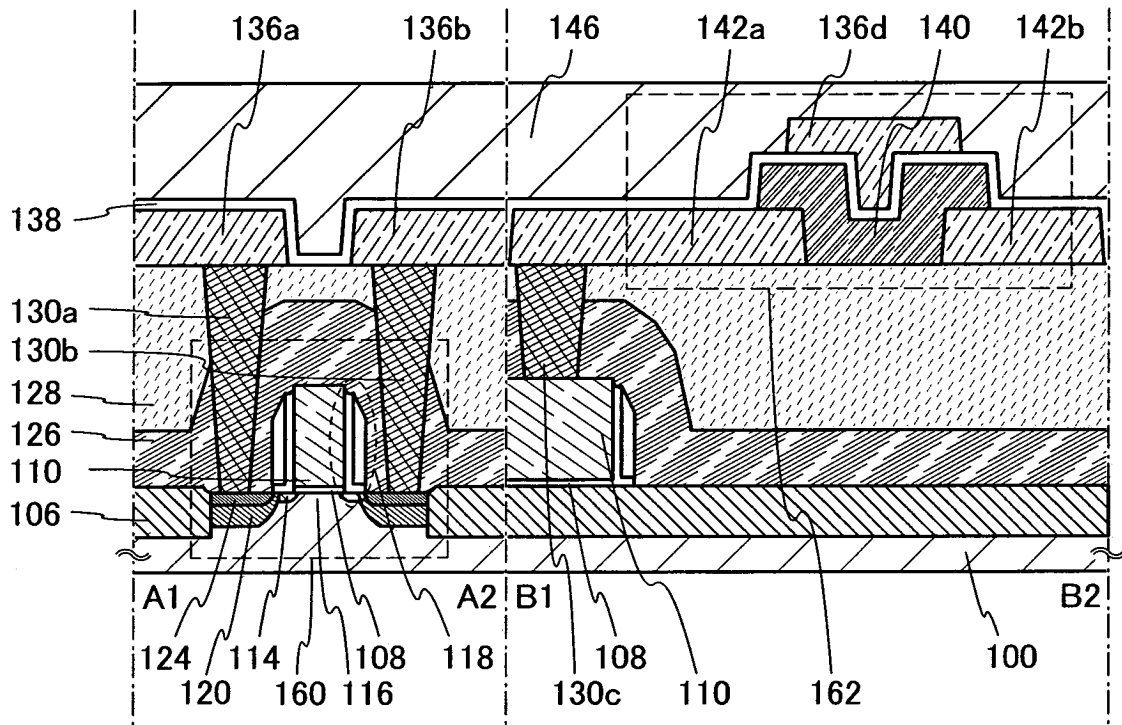


FIG. 9B

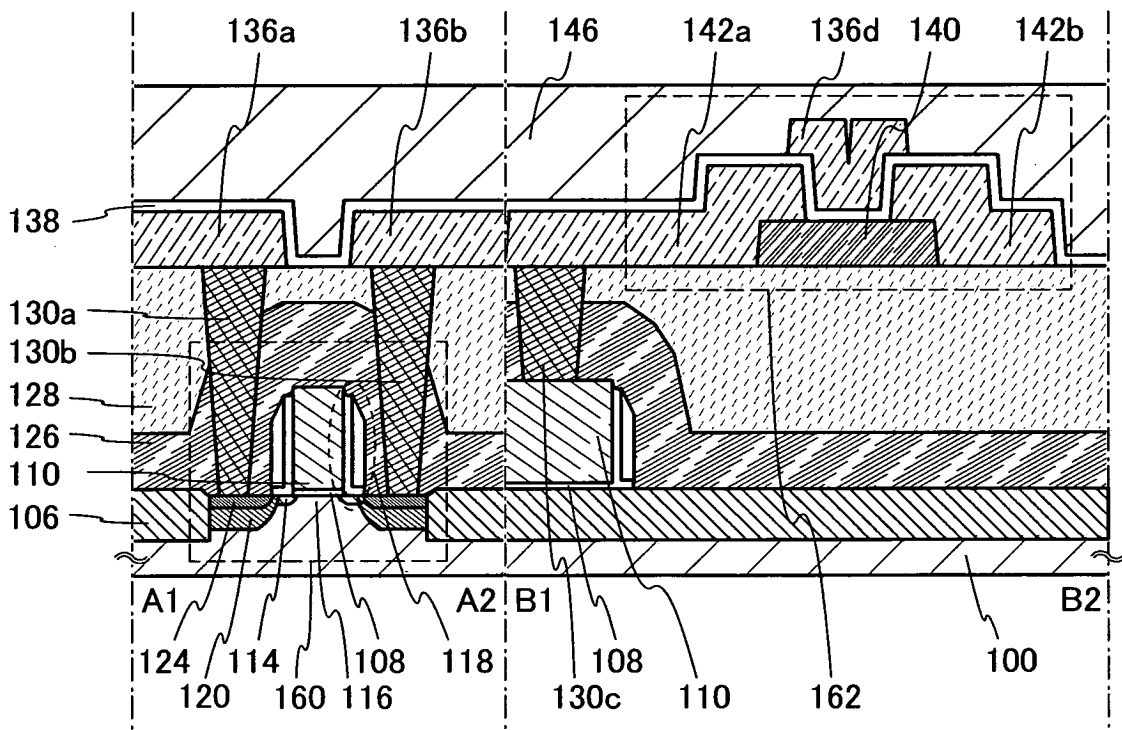


FIG. 10A

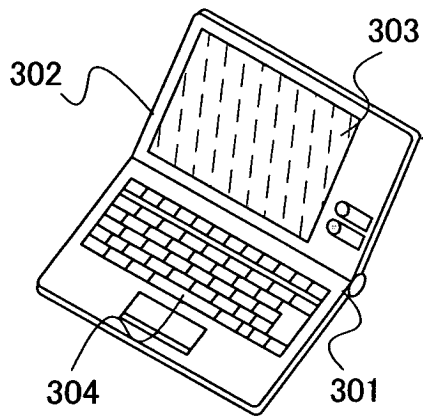


FIG. 10D

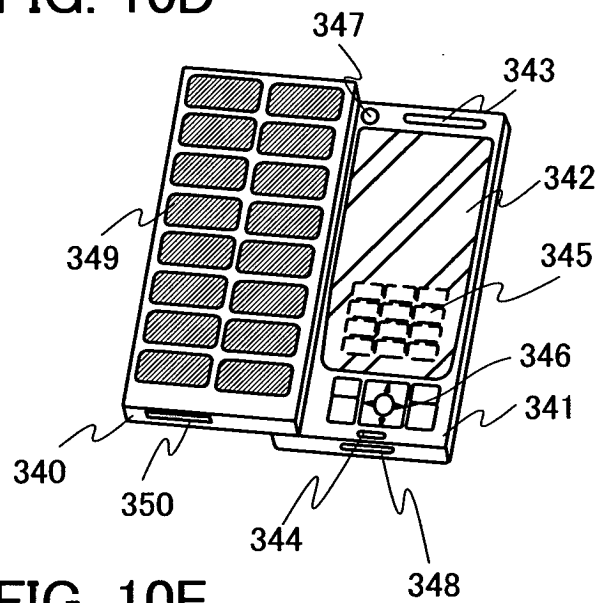


FIG. 10B

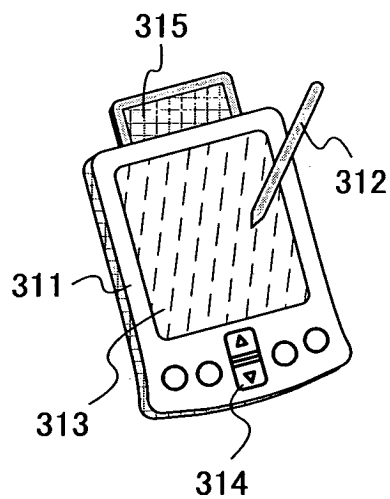


FIG. 10E

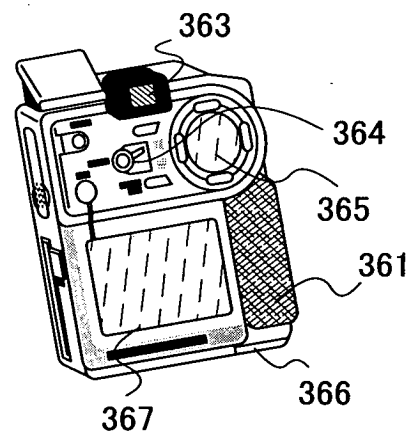


FIG. 10C

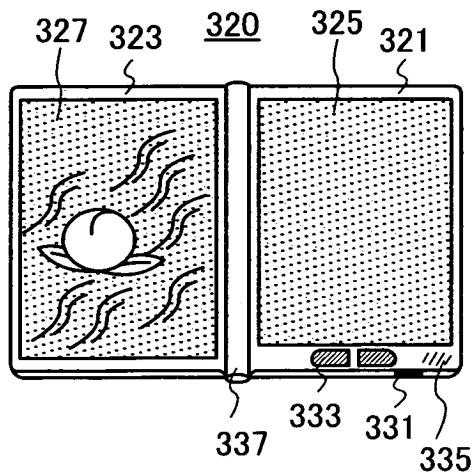


FIG. 10F

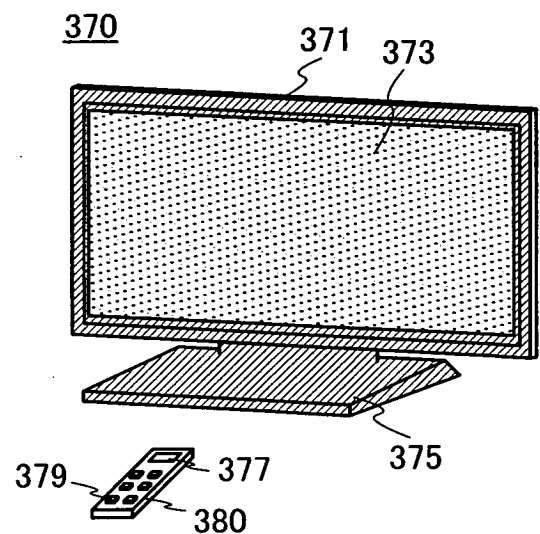


FIG. 11

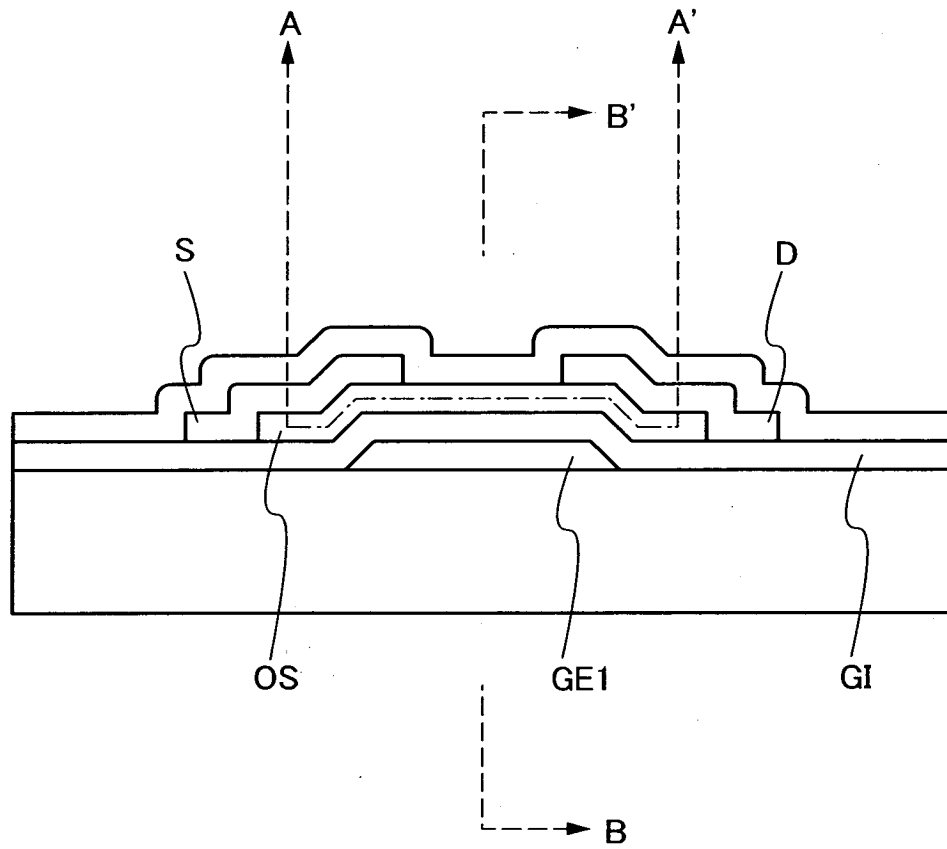


FIG. 12A

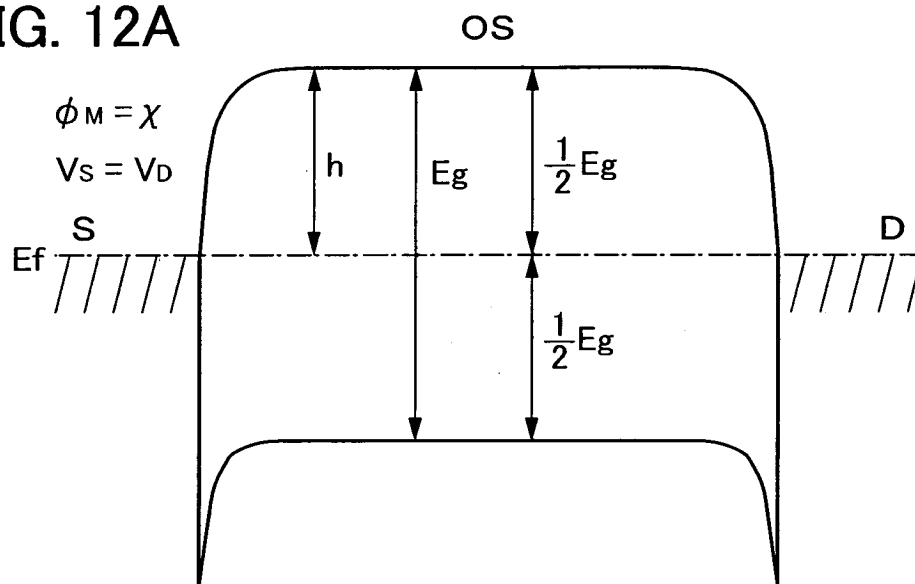


FIG. 12B

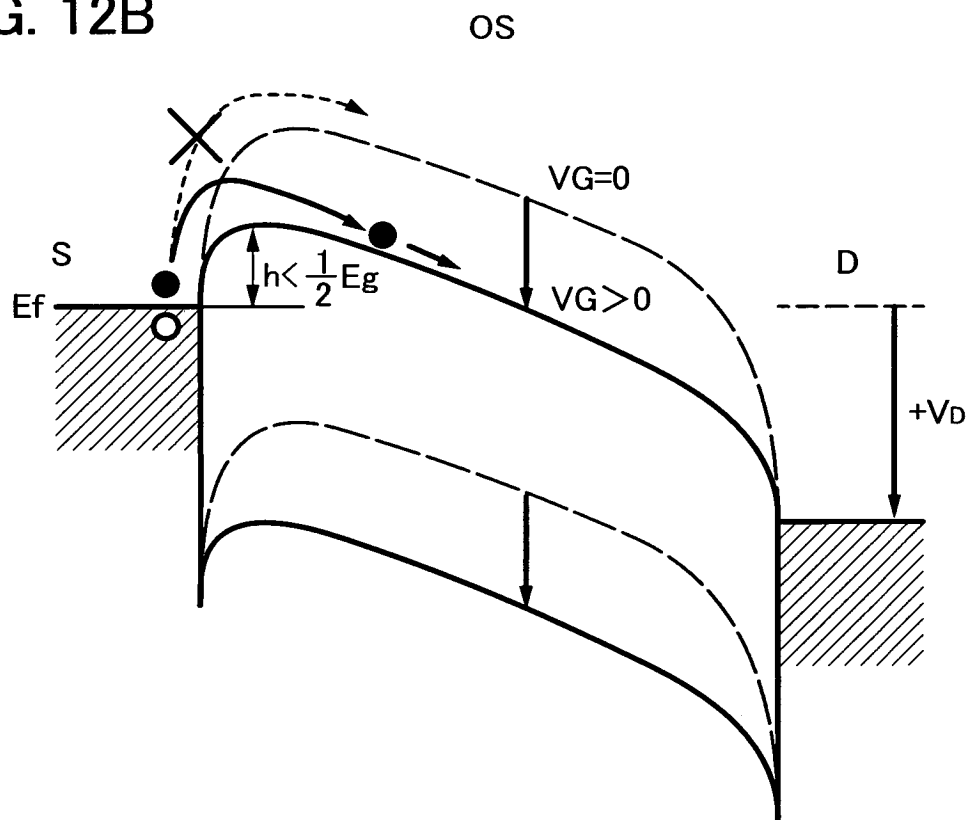


FIG. 13A

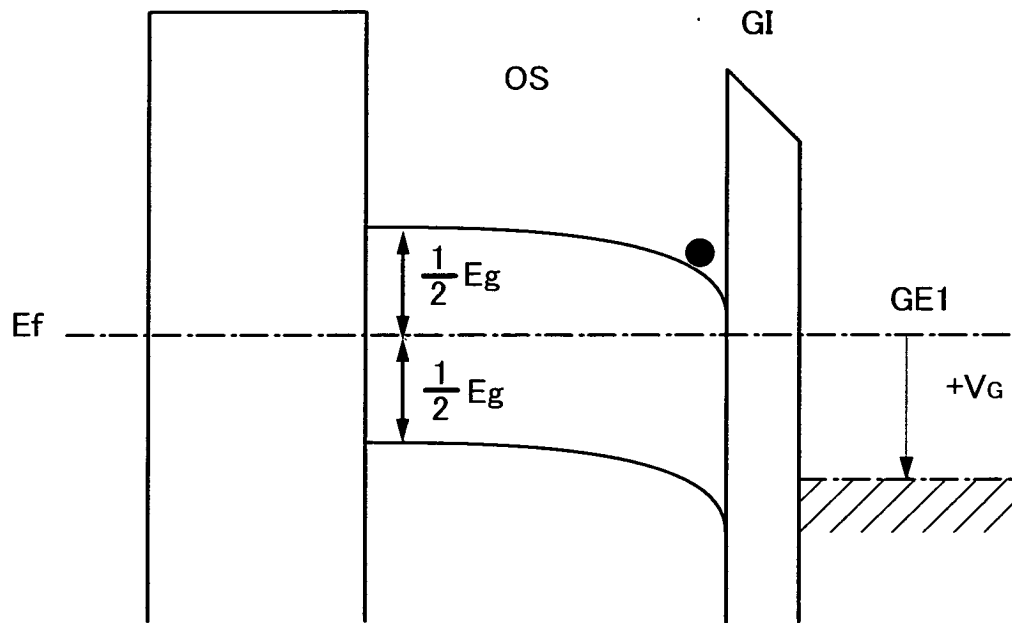


FIG. 13B

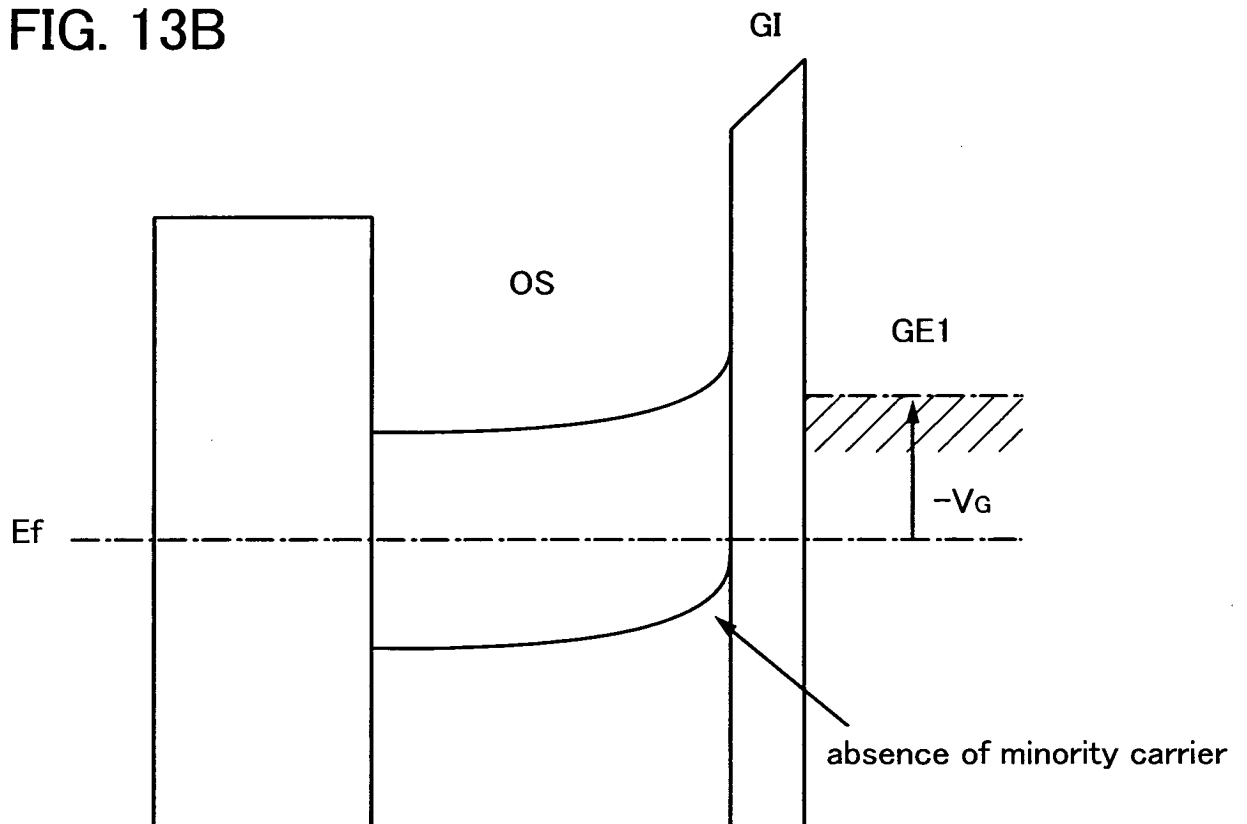


FIG. 14

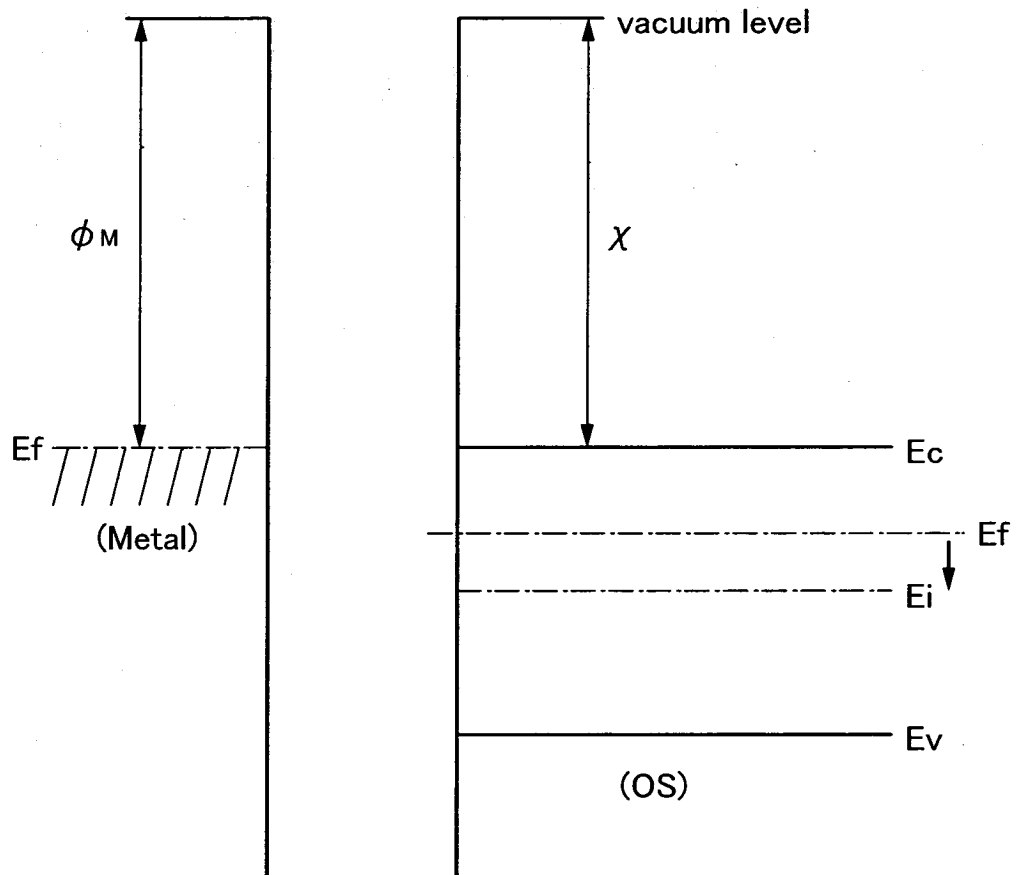


FIG. 15A

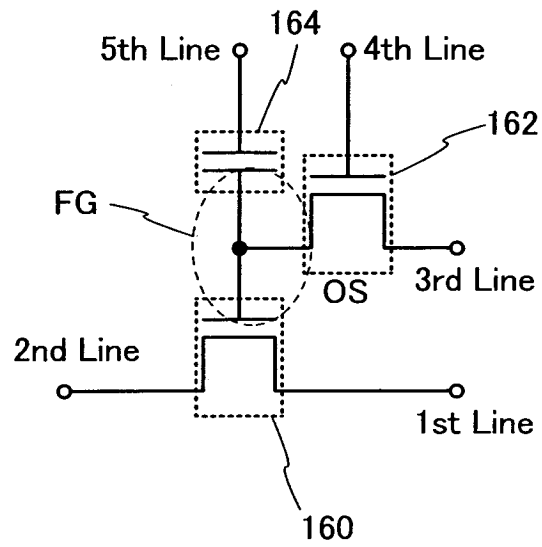


FIG. 15B

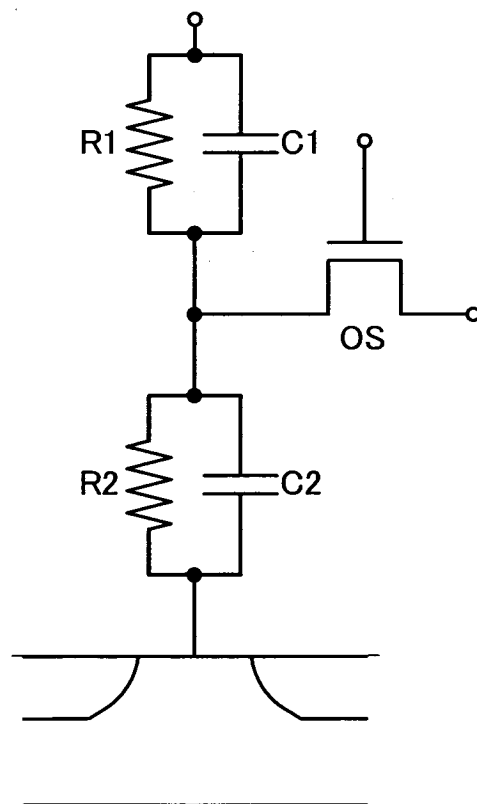


FIG. 16

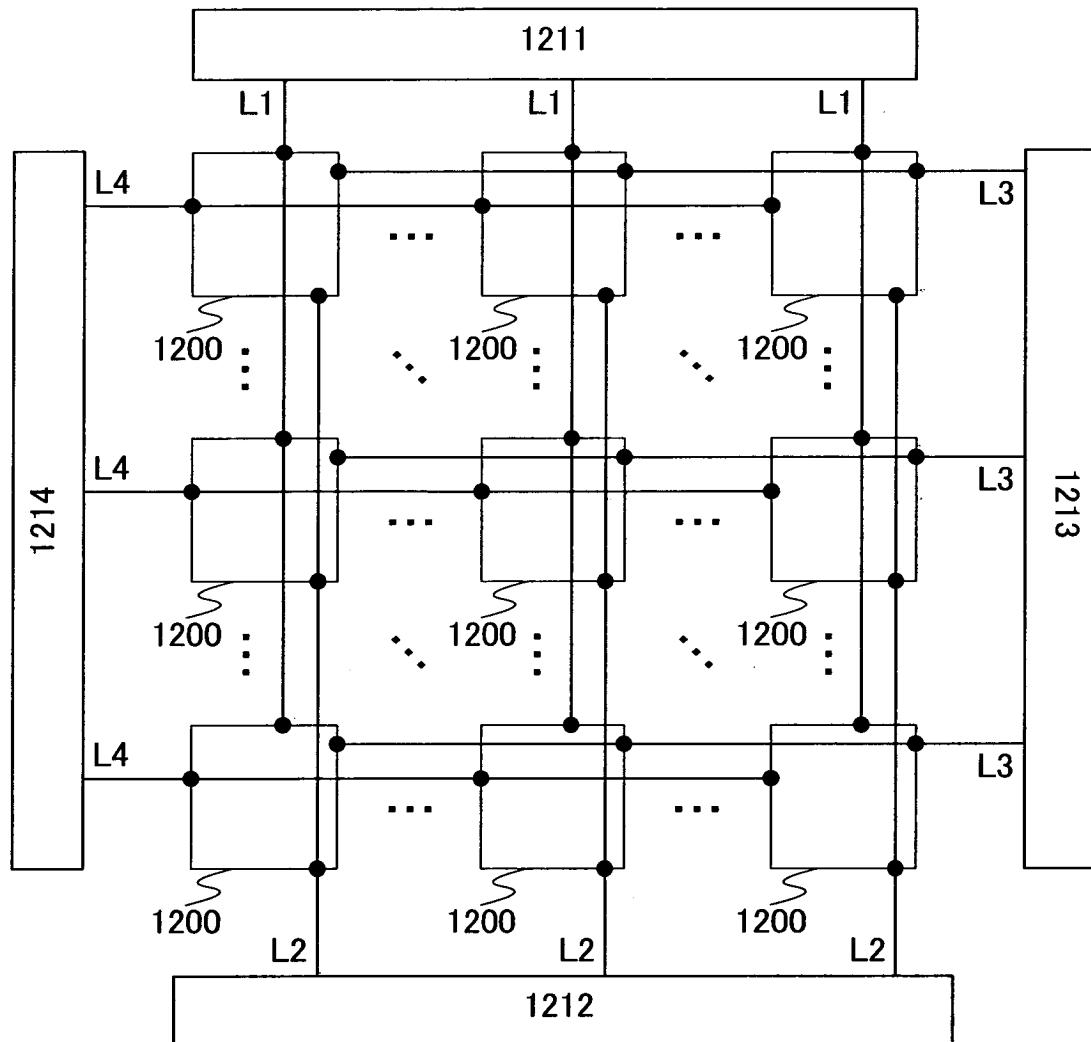


FIG. 17A

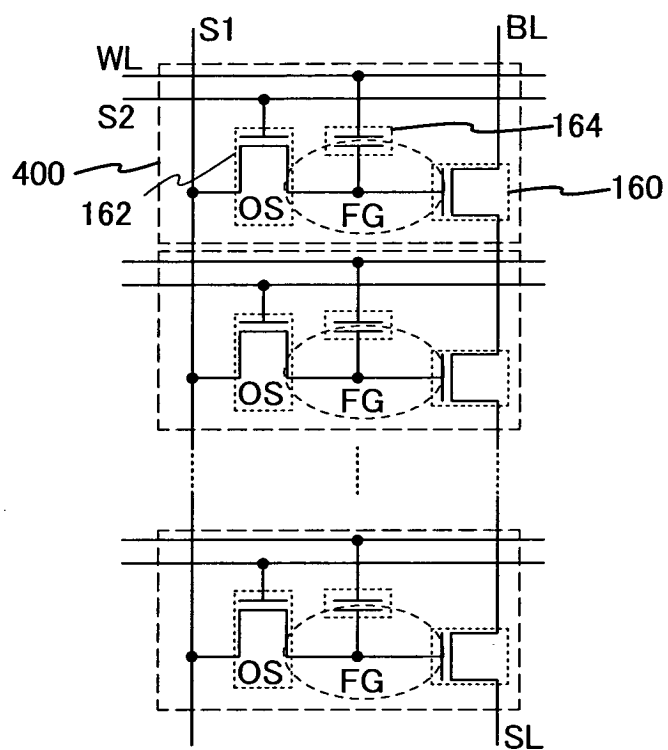


FIG. 17B

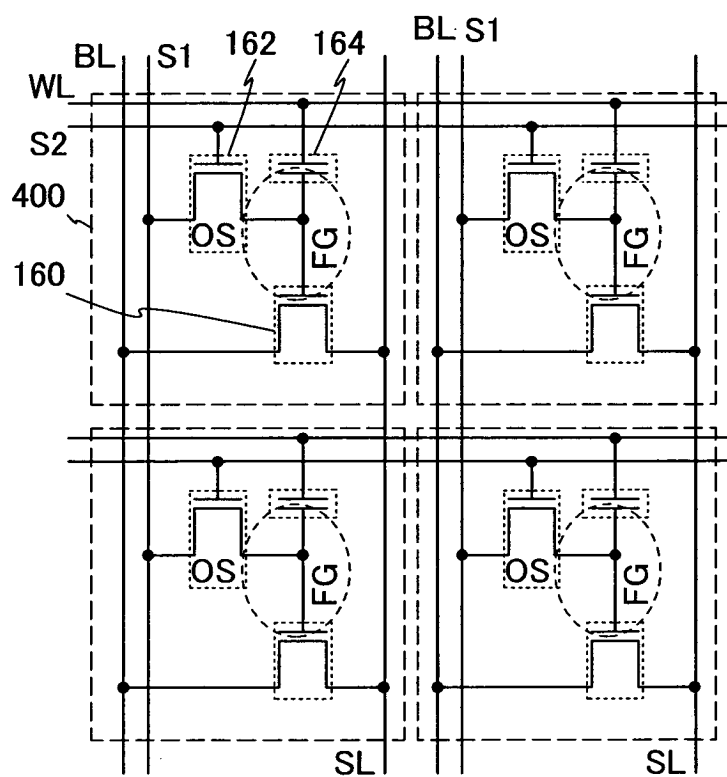


FIG. 18A

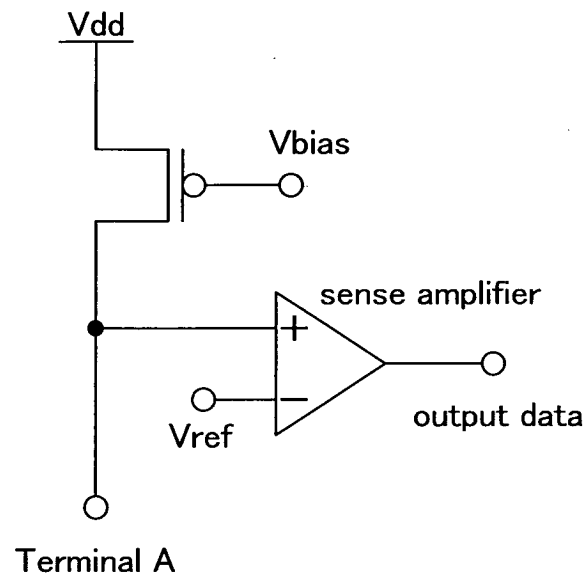


FIG. 18B

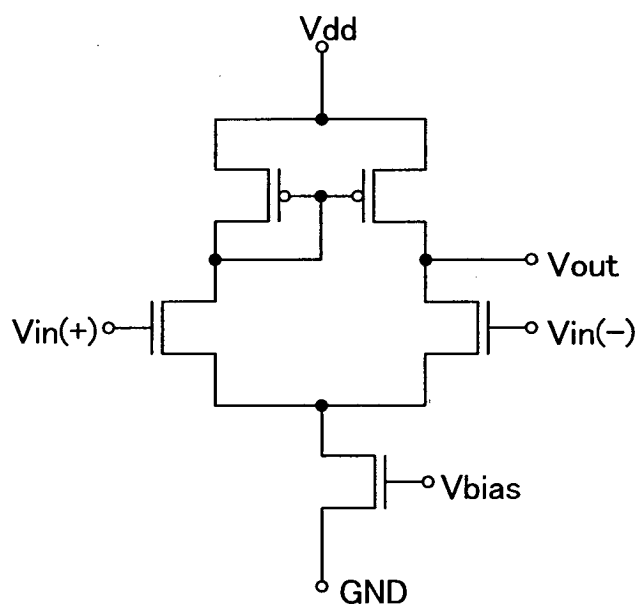


FIG. 18C

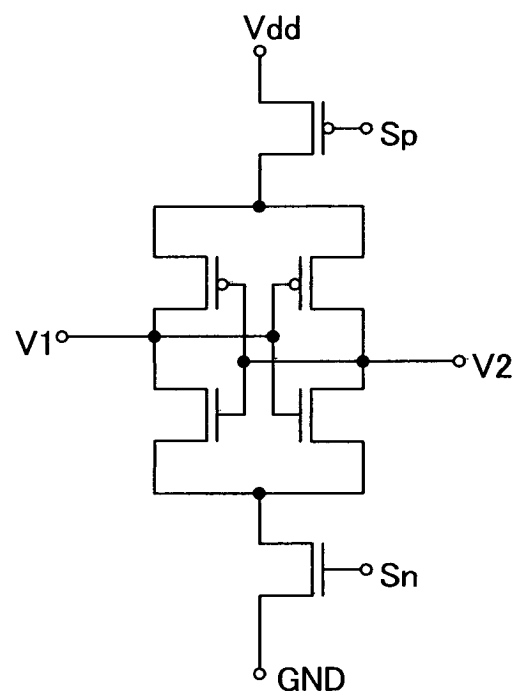


FIG. 19

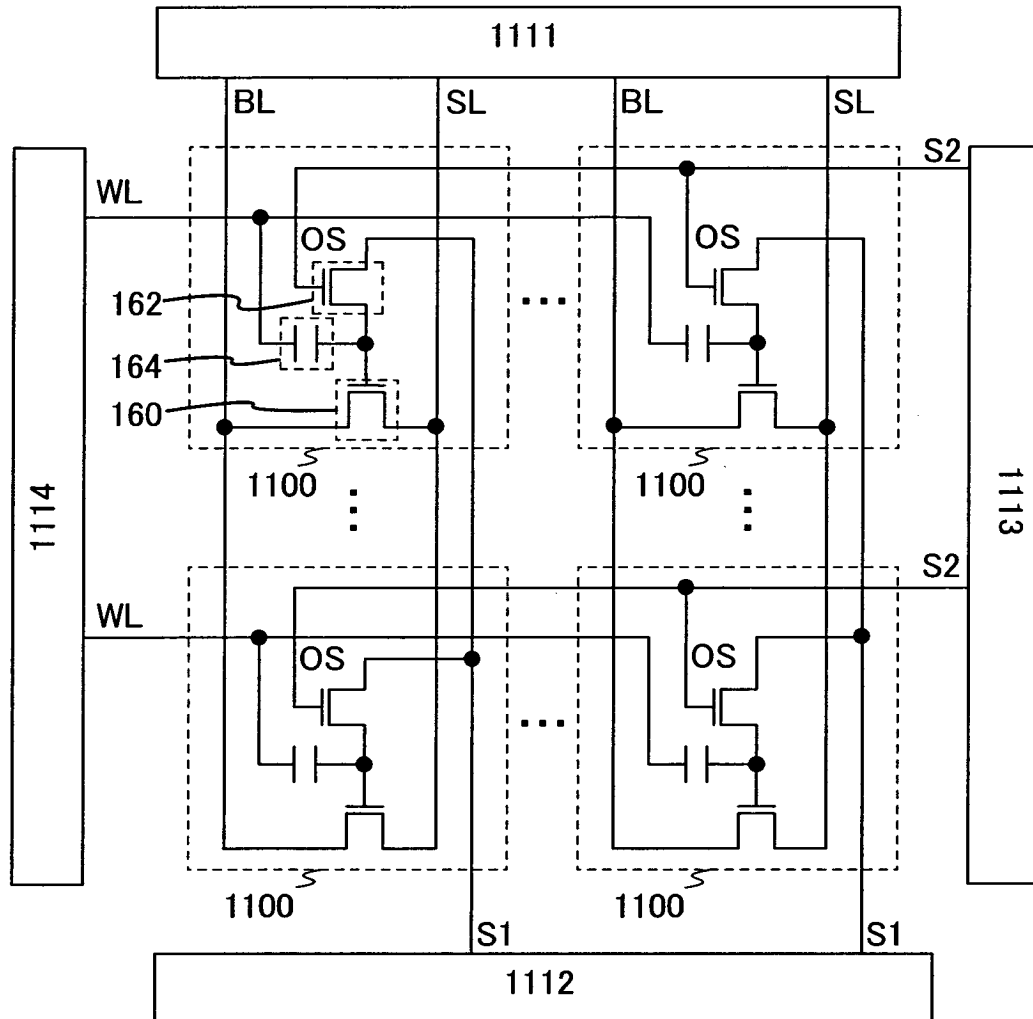


FIG. 20

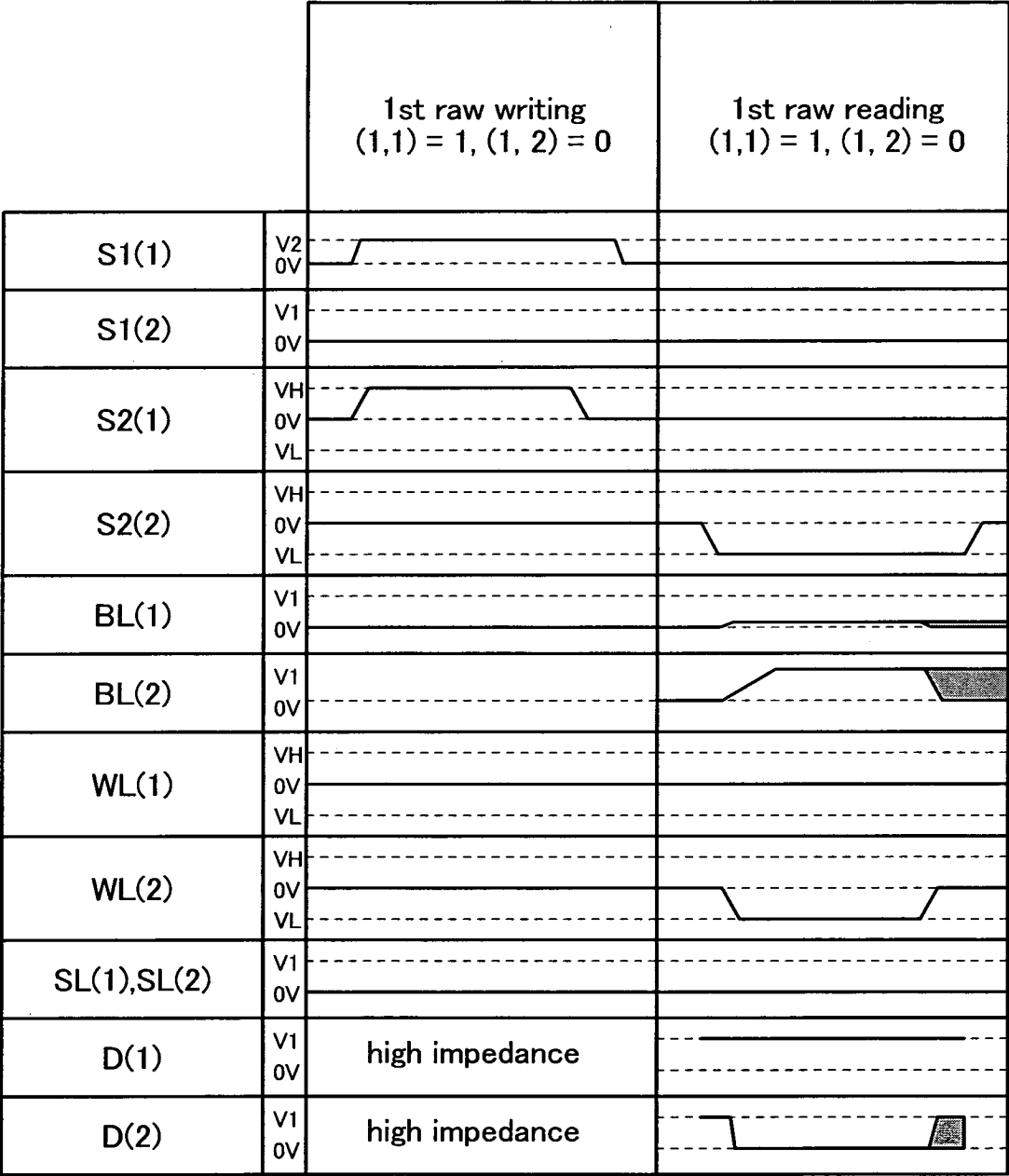


FIG. 21

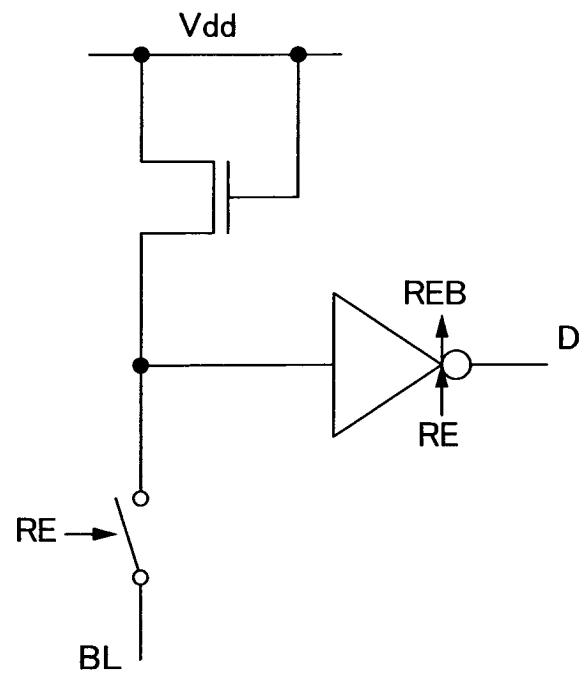


FIG. 22A

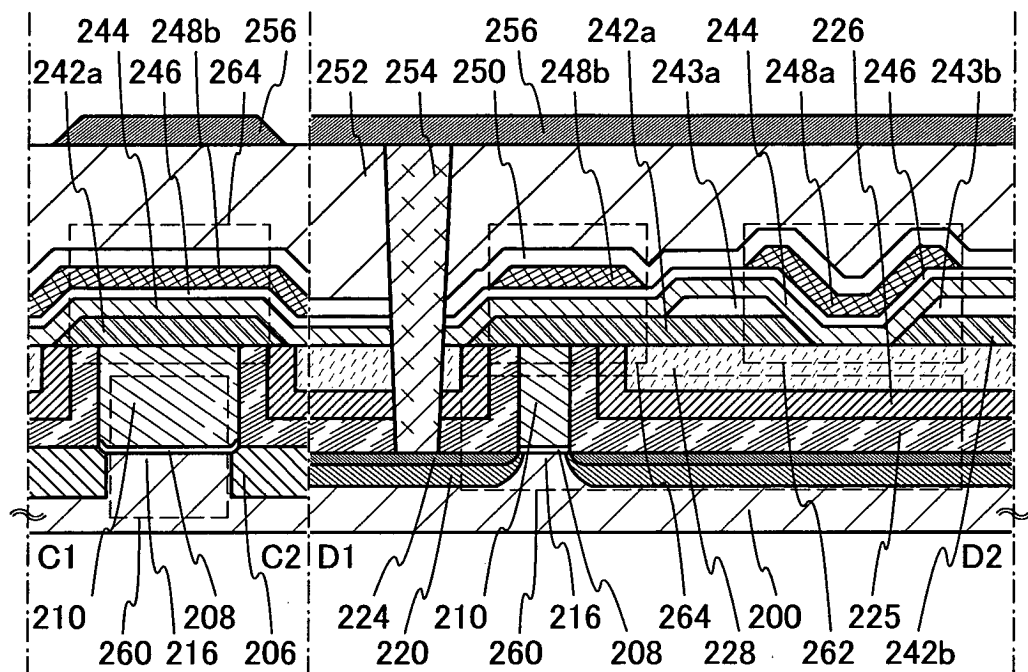


FIG. 22B

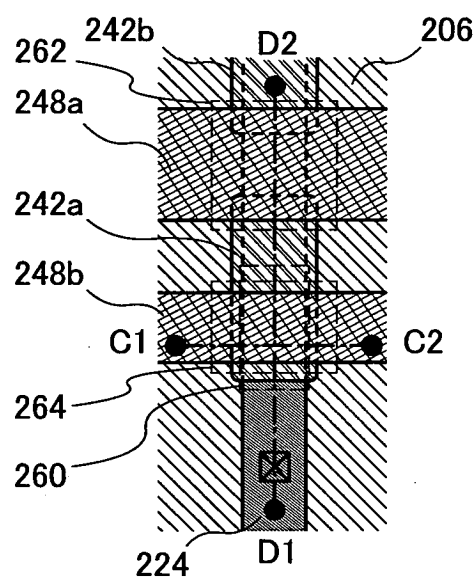


FIG. 23A

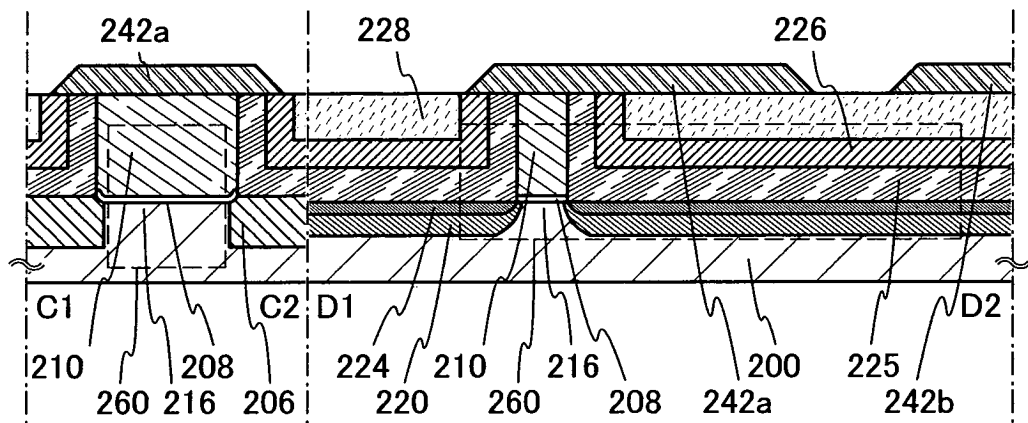


FIG. 23B

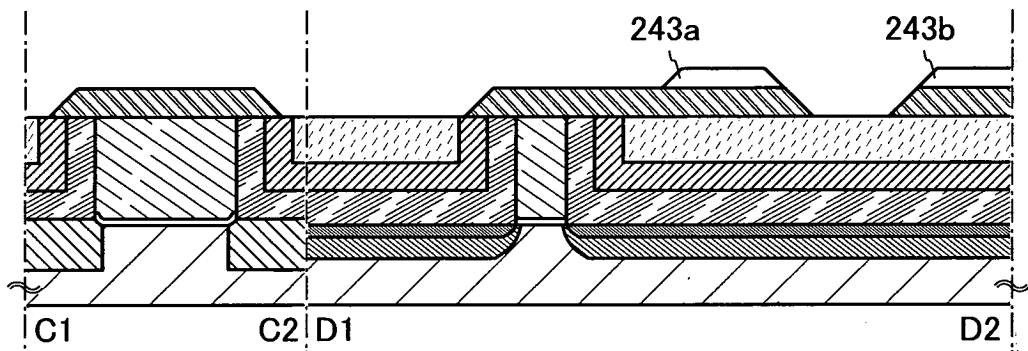


FIG. 23C

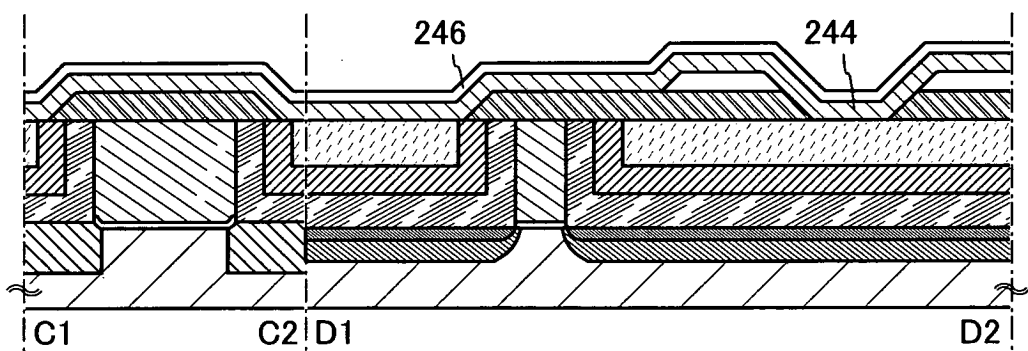


FIG. 23D

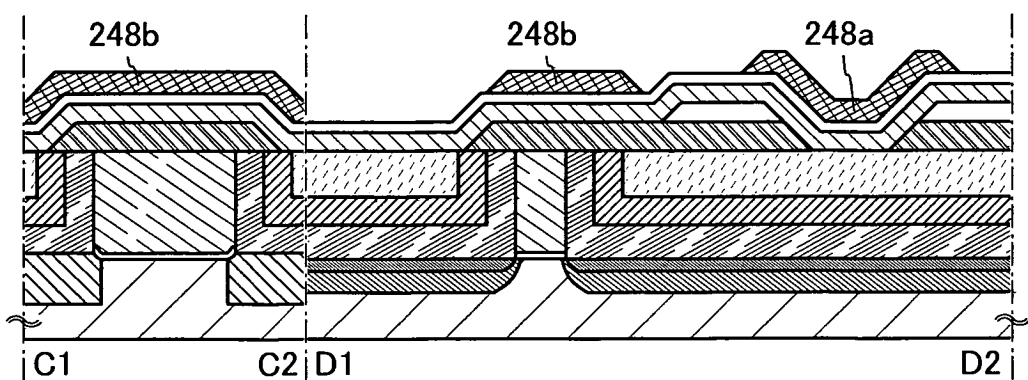


FIG. 24A

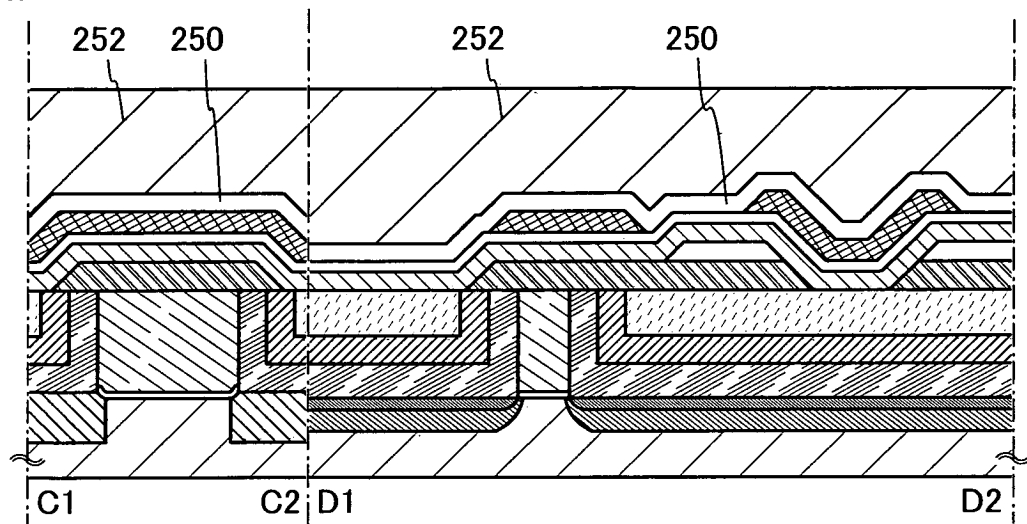


FIG. 24B

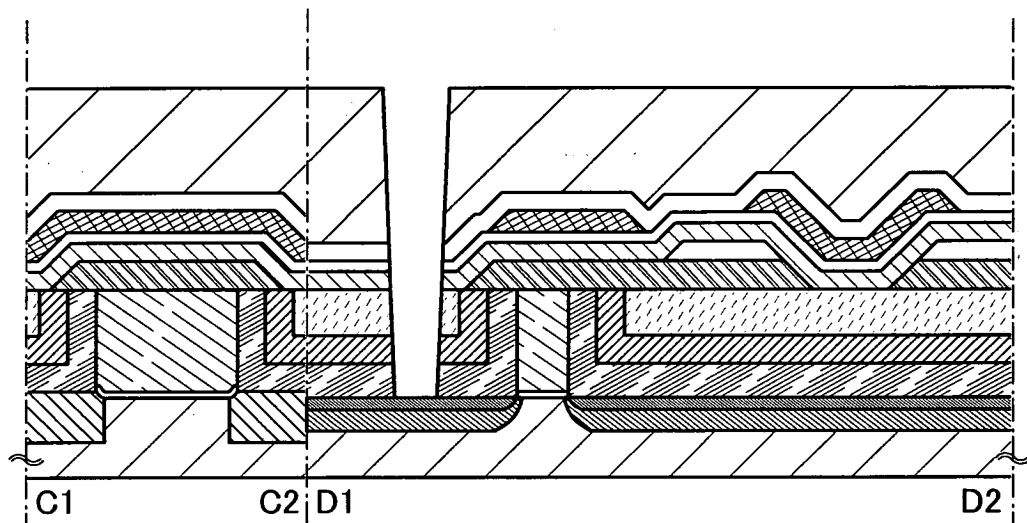


FIG. 24C

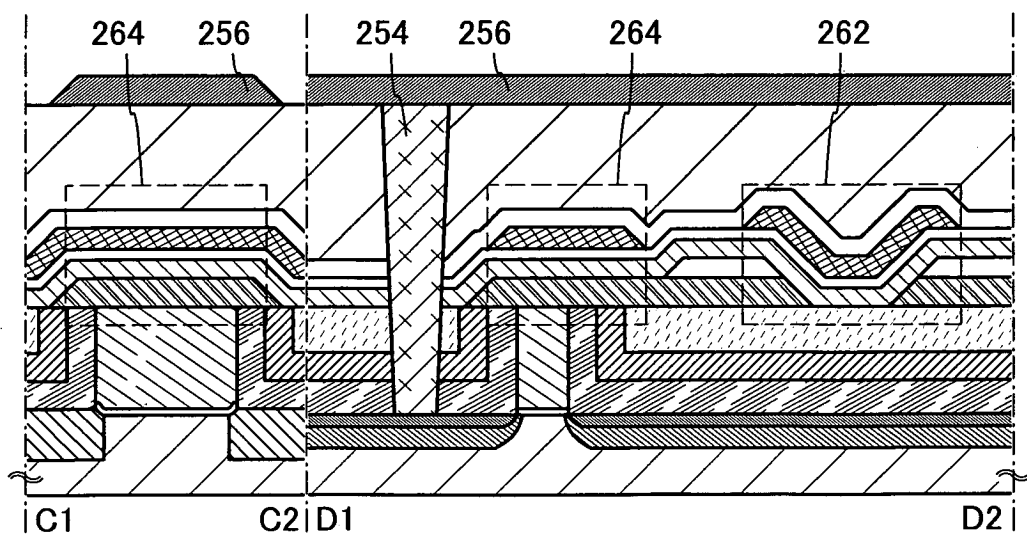


FIG. 25

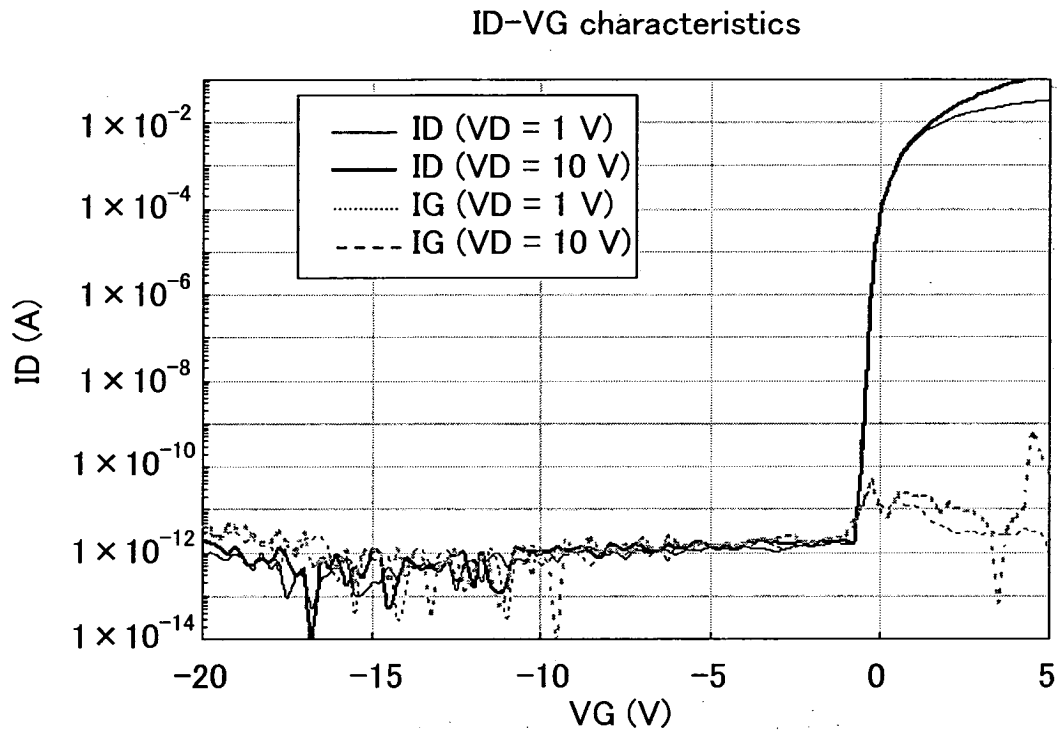


FIG. 26

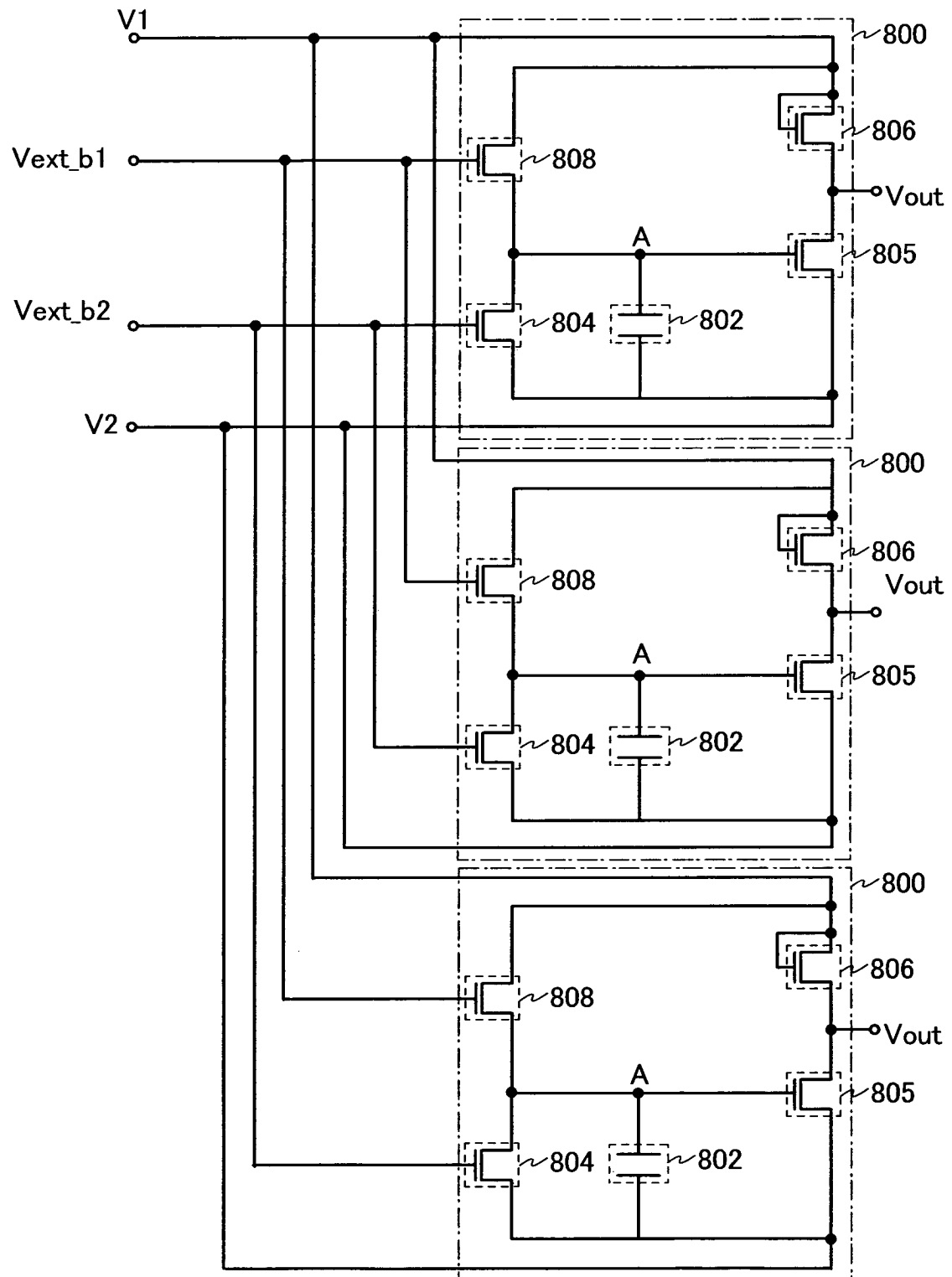


FIG. 27

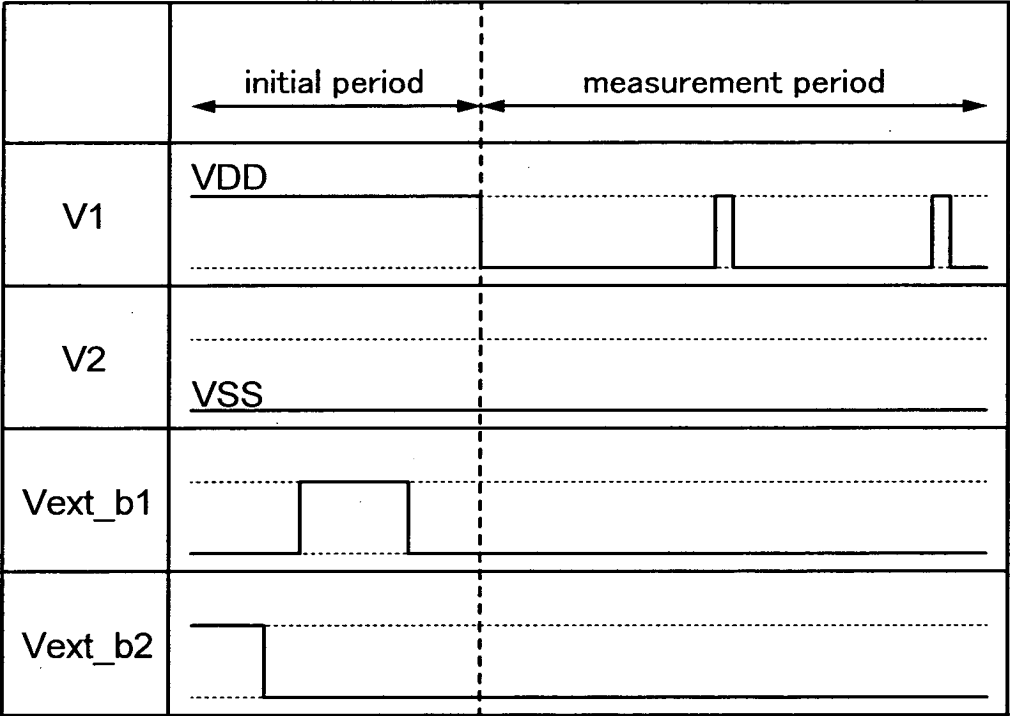


FIG. 28

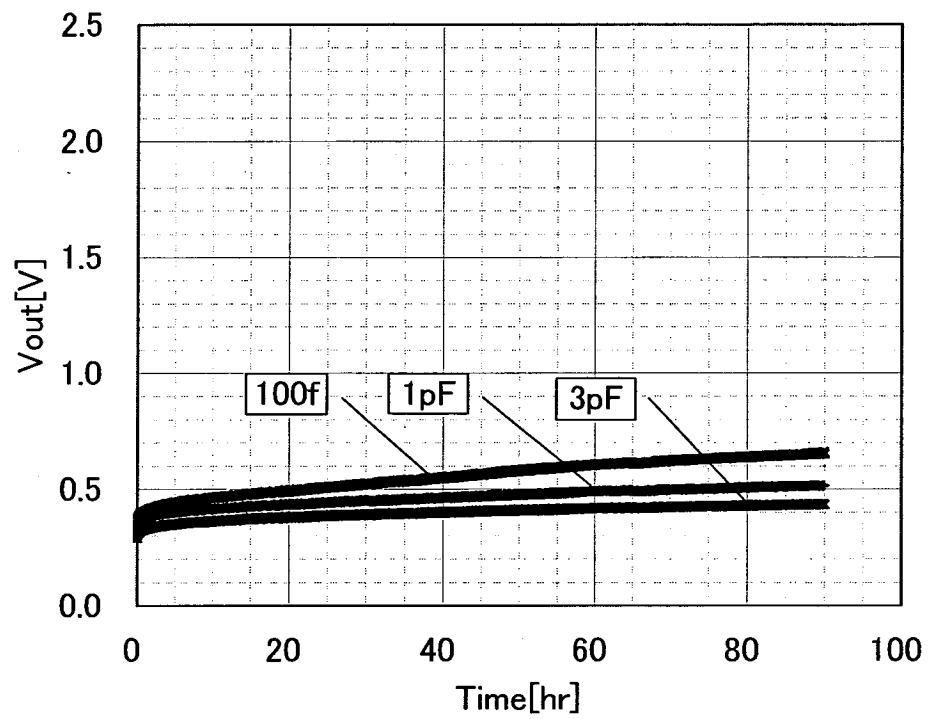


FIG. 29

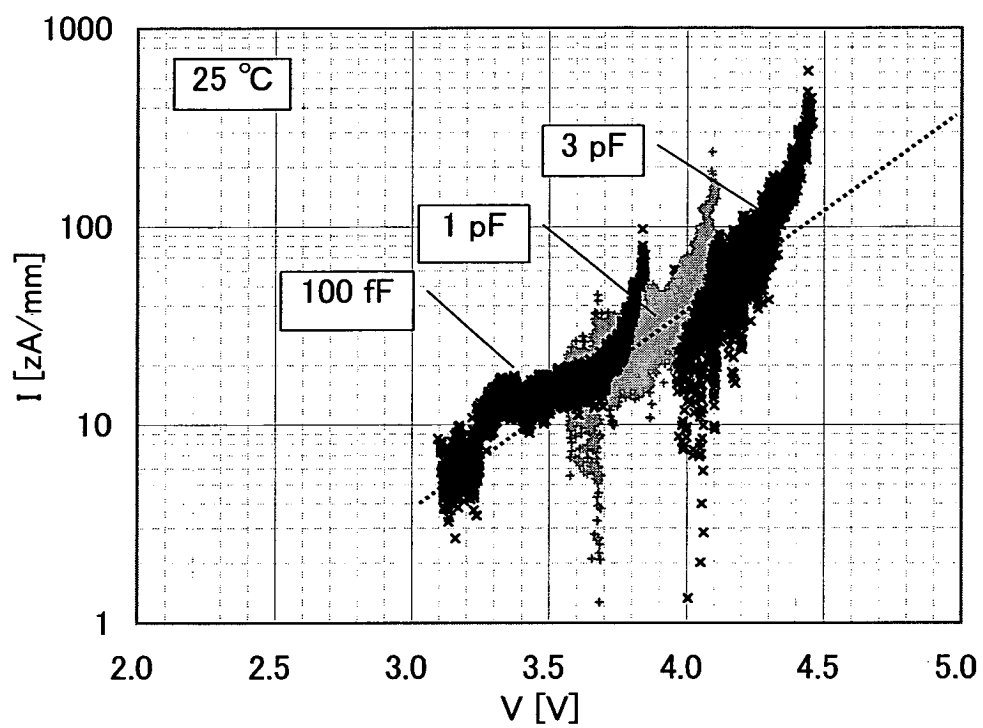


FIG. 30

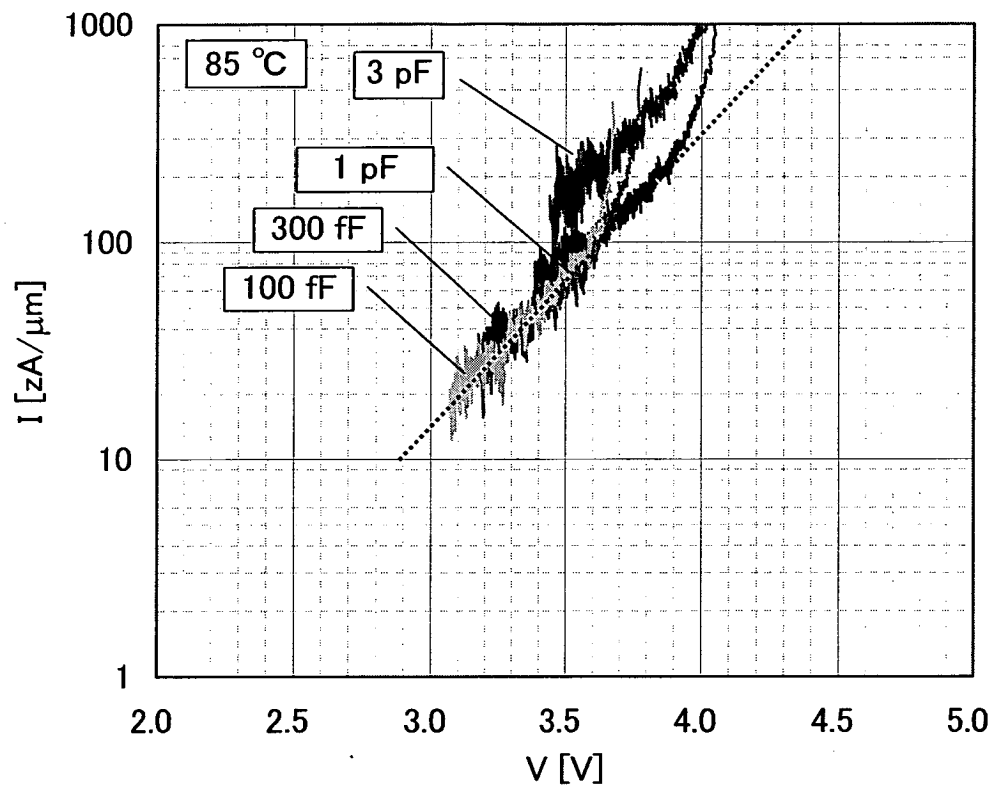
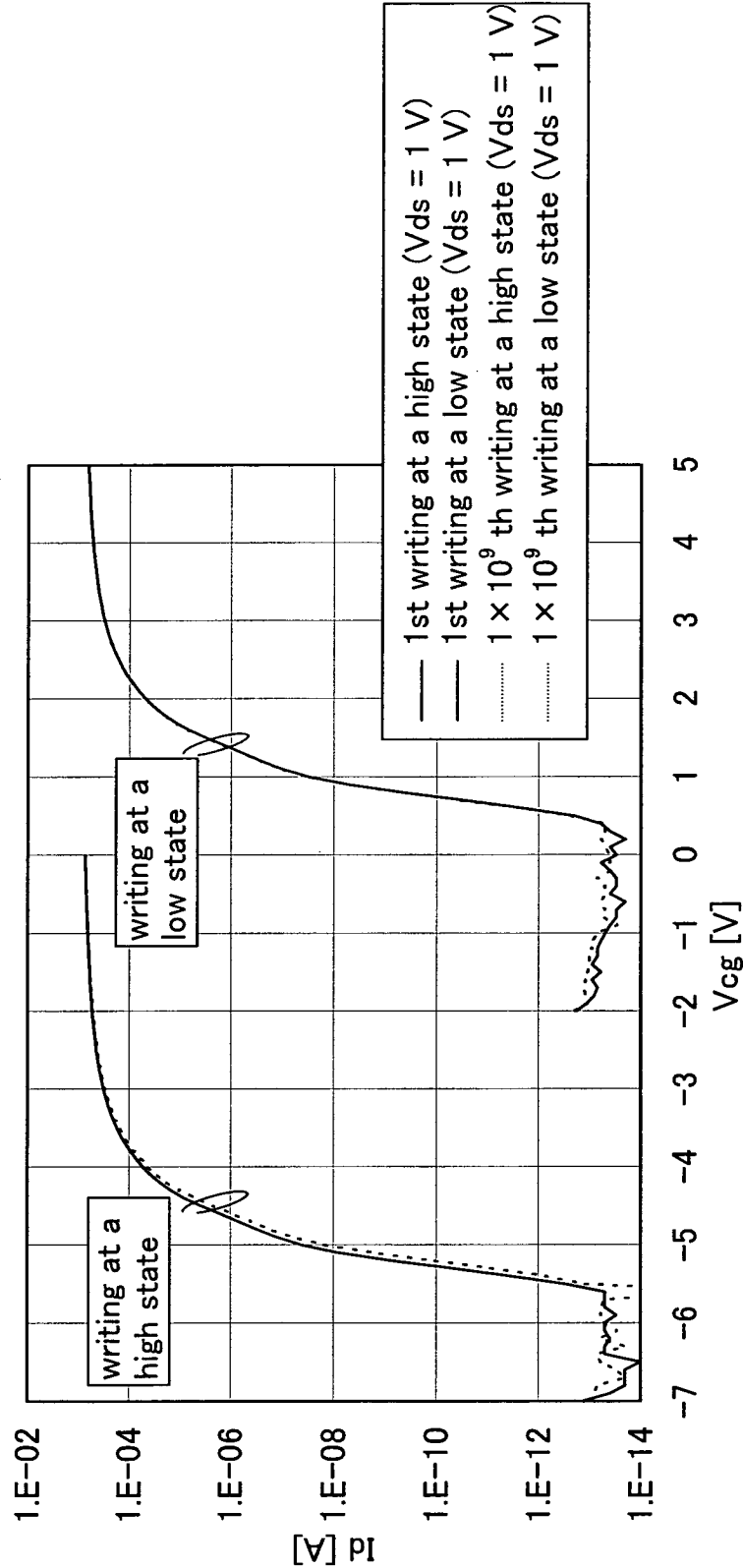


FIG. 31



EXPLANATION OF REFERENCE

100: substrate, 102: protective layer, 104: semiconductor region, 106: element isolation insulating layer, 108: gate insulating layer, 110: gate electrode, 112: insulating layer, 114: impurity region, 116: channel formation region, 118: sidewall insulating layer, 120: high-concentration impurity region, 122: metal layer, 124: metal compound region, 126: interlayer insulating layer, 128: interlayer insulating layer, 130a: source/drain electrode, 130b: source/drain electrode, 130c: electrode, 132: insulating layer, 134: conductive layer, 136a: electrode, 136b: electrode, 136c: electrode, 136d: gate electrode, 138: gate insulating layer, 140: oxide semiconductor layer, 142a: source/drain electrode, 142b: source/drain electrode, 144: protective insulating layer, 146: interlayer insulating layer, 148: conductive layer, 150a: electrode, 150b: electrode, 150c: electrode, 150d: electrode, 150e: electrode, 152: insulating layer, 154a: electrode, 154b: electrode, 154c: electrode, 154d: electrode, 160: transistor, 162: transistor, 164: a capacitor, 200: substrate, 206: element isolation insulating layer, 208: gate insulating layer, 210: gate electrode, 216: channel formation region, 220: high concentration impurity region, 224: metal compound region, 225: interlayer insulating layer, 226: interlayer insulating layer, 228: interlayer insulating layer, 242a: drain electrode, 242b: drain electrode, 243a: insulating layer, 243b: insulating layer, 244: oxide semiconductor layer, 246: gate insulating layer, 248a: gate electrode, 248b: electrode, 250: interlayer insulating layer, 252: interlayer insulating layer, 254: drain electrode, 256: line, 260: transistor, 262: transistor, 264: capacitor, 301: main body, 302: housing, 303: display portion, 304: keyboard, 311: main body, 312: stylus, 313: display portion, 314: operation button, 315: external interface, 320: e-book reader, 321: housing, 323: housing, 325: display portion, 327: display portion, 331: power switch, 333: operation key, 335: speaker, 337: hinge, 340: housing, 341: housing, 342: display panel, 343: speaker, 344: microphone, 345: operation key, 346: pointing device, 347: camera lens, 348: external connection terminal, 349: solar battery cell, 350: external memory slot, 361: main body, 363: eyepiece portion, 364: operation switch, 365: display portion (B), 366: battery, 367: display portion (A), 370: television set, 371: housing, 373: display portion, 375: stand, 377: display portion, 379: operation key, 380: remote controller, 400: memory cell, 800: measurement system, 802: capacitor, 802a: capacitor, 802b: capacitor, 802c: capacitor, 804: transistor, 805: transistor, 806: transistor, 808: transistor, 1100: memory cell, 1111: first driver circuit; 1112: second driver circuit, 1113: third driver circuit, 1114: fourth driver circuit, 1200: memory cell, 1211: first driver circuit; 1212: second driver circuit, 1213: third driver circuit, and 1214: fourth driver circuit.